mXT336UD-MAU002 2.0

maXTouch 336-node Touchscreen Controller

maXTouch® Adaptive Sensing Technology

- Up to 14 X (transmit) lines and 24 Y (receive) lines for use by a touchscreen and/or key array (see Section 4.3 “Permitted Configurations”)
- A maximum of 336 nodes can be allocated to the touch sensor
- Touchscreen size of 7.11 inches (16:9 aspect ratio), assuming a sensor electrode pitch of 6.5 mm. Other sizes are possible with different electrode pitches and appropriate sensor material
- Multiple touch support with up to 10 concurrent touches tracked in real time

Keys

- Up to 16 nodes can be allocated as mutual capacitance sensor keys in addition to the touchscreen, defined as 1 key array (subject to availability of X and Y lines and other configurations)
- Adjacent Key Suppression (AKS) technology is supported for false key touch prevention

Touch Sensor Technology

- Discrete/out-cell support including glass and PET film-based sensors
- On-cell/touch-on display support including TFT, LCD (ITPS, IPS) and OLED
- Synchronization with display refresh timing capability
- Support for standard (for example, Diamond) and proprietary sensor patterns (review of designs by Microchip or a Microchip-qualified touch sensor module partner is recommended)

Front Panel Material

- Works with PET or glass, including curved profiles (configuration and stack-up to be approved by Microchip or a Microchip-qualified touch sensor module partner)
- 10 mm glass (or 5 mm PMMA) with bare finger (dependent on sensor size, touch size, configuration and stack-up)
- 6 mm glass (or 3 mm PMMA) with multi-finger 5 mm glove (2.7 mm PMMA equivalent) (dependent on sensor size, touch size, configuration and stack-up)

Touch Performance

- Moisture/Water Compensation
  - No false touch with condensation or water drop up to 22 mm diameter
  - One-finger tracking with condensation or water drop up to 22 mm diameter
- Mutual capacitance and self capacitance measurements supported for robust touch detection
- P2P mutual capacitance measurements supported for extra sensitive multi-touch sensing
- Noise suppression technology to combat ambient and power-line noise
  - Up to 240 V_{PP} between 1 Hz and 1 kHz sinusoidal waveform (no touches)
  - IEC 61000-4-6, 7 Vrms, Class A (normal touch operation) conducted noise immunity
- Stylus Support
  - Supports passive stylus with 1.5 mm contact diameter, subject to configuration, stack-up, and sensor design
- Scan Speed
  - Typical report rate for 10 touches ≥90 Hz (subject to configuration)
  - Initial touch latency <18 ms for first touch from idle (subject to configuration)
  - Configurable to allow for power and speed optimization
- Touch panel failure detection
  - Automatic touch sensor diagnostics during run time to support the implementation of safety critical features
  - Diagnostics reported using dedicated output pin or by standard Object Protocol messages
  - Configurable test limits

Enhanced Algorithms

- Lens bending algorithms to remove display noise
- Touch suppression algorithms to remove unintentional large touches, such as palm
- Palm Recovery Algorithm for quick restoration to normal state

Data Store

- 60-byte CRC-checksummed data area for use as a run-time Product Data Store Area
- Up to 64 bytes of user's custom data (not CRC checksummed)

Device Encryption

- Encrypted configuration parameters and touch coordinate reports (OBP messages) using customer's own security key

Power Saving

- Programmable timeout for automatic transition from Active to Idle state
- Pipelined analog sensing detection and digital processing to optimize system power efficiency

Application Interfaces

- I^2C client interface for main communication with the device, with support for Standard mode (up to 100 kHz), Fast mode (up to 400 kHz), Fast-mode Plus (up to 1 MHz)
- Interrupt to indicate when a message is available
- Additional SPI Debug Interface to read the raw data for tuning and debugging purposes

Power Supply

- Digital (Vdd) 3.3V nominal
- Digital I/O (VddIO) 3.3V nominal
- Analog (AVdd) 3.3V nominal
- High voltage internal X line drive (XVdd) 6.6V with internal voltage pump

Package

- 56-pin XQFN 6 × 6 × 0.4 mm, 0.35 mm pitch

Operating Temperature

- –40°C to +85°C

Design Services

- Review of device configuration, stack-up and sensor patterns

PIN CONFIGURATION

Pin Configuration – 56-pin XQFN

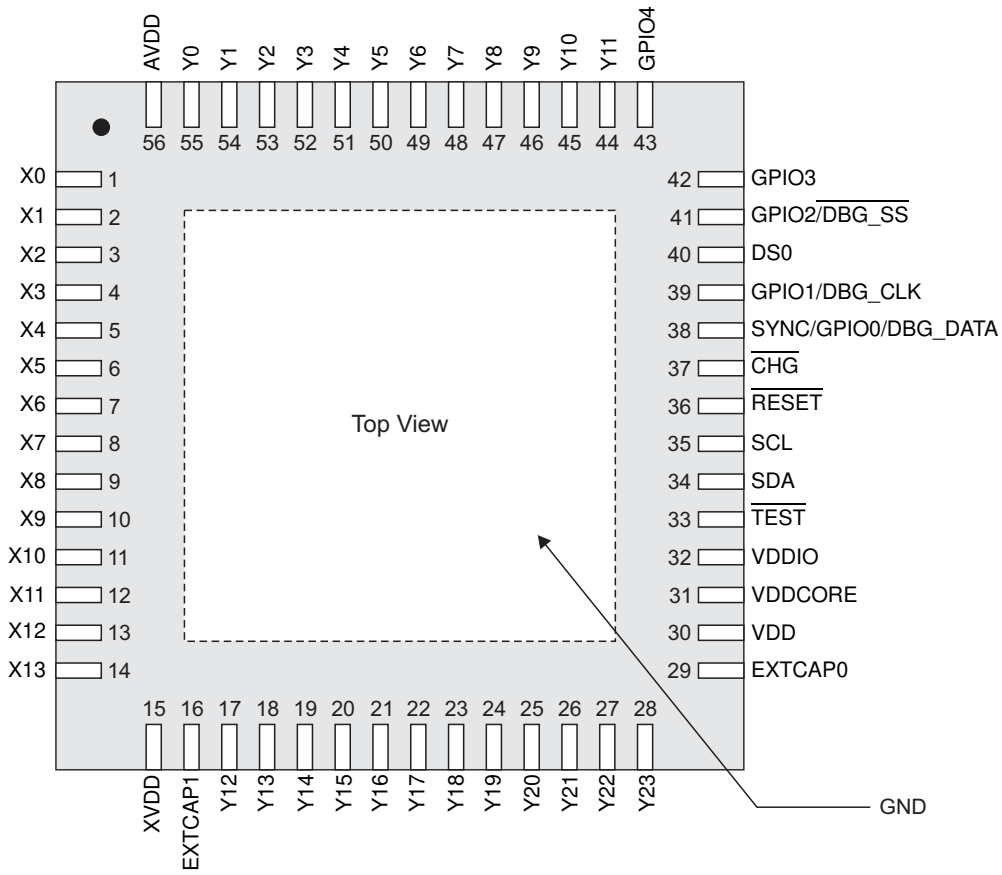

TABLE 1: PIN LISTING – 56-PIN XQFN

Pin	Name	Type	Supply	Description	If Unused...
1	X0	S	XVdd	X line connection	Leave open
2	X1	S	XVdd	X line connection	Leave open
3	X2	S	XVdd	X line connection	Leave open
4	X3	S	XVdd	X line connection	Leave open
5	X4	S	XVdd	X line connection	Leave open
6	X5	S	XVdd	X line connection	Leave open
7	X6	S	XVdd	X line connection	Leave open
8	X7	S	XVdd	X line connection	Leave open
9	X8	S	XVdd	X line connection	Leave open
10	X9	S	XVdd	X line connection	Leave open
11	X10	S	XVdd	X line connection	Leave open
12	X11	S	XVdd	X line connection	Leave open
13	X12	S	XVdd	X line connection	Leave open
14	X13	S	XVdd	X line connection	Leave open
15	XVDD	P	–	X line drive power	–
16	EXTCAP1	P	–	Voltage doubler – connect to EXTCAP0 via capacitor; see Section 2.2.5 “XVdd”	Leave open
17	Y12	S	AVdd	Y line connection	Leave open
18	Y13	S	AVdd	Y line connection	Leave open
19	Y14	S	AVdd	Y line connection	Leave open
20	Y15	S	AVdd	Y line connection	Leave open
21	Y16	S	AVdd	Y line connection	Leave open
22	Y17	S	AVdd	Y line connection	Leave open
23	Y18	S	AVdd	Y line connection	Leave open
24	Y19	S	AVdd	Y line connection	Leave open
25	Y20	S	AVdd	Y line connection	Leave open
26	Y21	S	AVdd	Y line connection	Leave open
27	Y22	S	AVdd	Y line connection	Leave open
28	Y23	S	AVdd	Y line connection	Leave open
29	EXTCAP0	P	–	Voltage doubler – connect to EXTCAP1 via capacitor; see Section 2.2.5 “XVdd”	Leave open
30	VDD	P	–	Digital power	–
31	VDDCORE	P	–	Digital core power	–
32	VDDIO	P	–	Digital IO interface power	–
33	$\overline{\text{TEST}}$	–	VddIO	Reserved for factory use; pull up to VddIO	–
34	SDA	OD	VddIO	I^2C Serial Data	–
35	SCL	OD	VddIO	I^2C Serial Clock	–
36	$\overline{\text{RESET}}$	I	VddIO	Reset low. Pull up to VddIO. Connection to host system is recommended	Pull up to VddIO
37	$\overline{\text{CHG}}$	OD	VddIO	State change interrupt. Pull up to VddIO Note: Briefly set (~100 ms) as an input after power-up/reset for diagnostic purposes	–

TABLE 1: PIN LISTING – 56-PIN XQFN (CONTINUED)

Pin	Name	Type	Supply	Description	If Unused...
38	SYNC	I	VddIO	External synchronization: frame synchronization (VSync) or pulse synchronization (HSync) (1)	–
	GPIO0	I/O	VddIO	General purpose IO; see Section 2.2.10 “GPIO Pins”	Connect to test point Input: Connect to GND Output: Leave open
	DBG_DATA	O		Debug Data	
39	GPIO1	I/O	VddIO	General purpose IO; see Section 2.2.10 “GPIO Pins”	Connect to test point Input: Connect to GND Output: Leave open
	DBG_CLK	O		Debug Clock	
40	DS0	O	Vdd	Driven Shield signal; used as guard track between X/Y signals and ground	Leave open
41	GPIO2	S	Vdd	General purpose IO; see Section 2.2.10 “GPIO Pins”	Leave open
	$\overline{\text{DBG\_SS}}$	O		Debug SS line	
42	GPIO3	S	Vdd	General purpose IO; see Section 2.2.10 “GPIO Pins”	Leave open
43	GPIO4	S	Vdd	General purpose IO; see Section 2.2.10 “GPIO Pins”	Leave open
44	Y11	S	AVdd	Y line connection	Leave open
45	Y10	S	AVdd	Y line connection	Leave open
46	Y9	S	AVdd	Y line connection	Leave open
47	Y8	S	AVdd	Y line connection	Leave open
48	Y7	S	AVdd	Y line connection	Leave open
49	Y6	S	AVdd	Y line connection	Leave open
50	Y5	S	AVdd	Y line connection	Leave open
51	Y4	S	AVdd	Y line connection	Leave open
52	Y3	S	AVdd	Y line connection	Leave open
53	Y2	S	AVdd	Y line connection	Leave open
54	Y1	S	AVdd	Y line connection	Leave open
55	Y0	S	AVdd	Y line connection	Leave open
56	AVDD	P	–	Analog power	–
Pad	GND	P	–	Exposed pad must be connected to GND	–

Note 1: The SYNC line can be used for either pulse synchronization or frame synchronization, but not both.

Key:

I	Input only	O	Output only	I/O	Input or output
OD	Open drain output	P	Ground or power	S	Sense pin

TABLE OF CONTENTS

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1.0 OVERVIEW OF MXT336UD-MAU002

The Microchip maXTouch family of touch controllers brings industry-leading capacitive touch performance to customer applications. The mXT336UD-MAU002 features the latest generation of Microchip adaptive sensing technology that utilizes a hybrid mutual and self capacitive sensing system in order to deliver unparalleled touch features and a robust user experience.

- **Patented capacitive sensing method** – The mXT336UD-MAU002 uses a unique charge-transfer acquisition engine to implement Microchip's patented capacitive sensing method. Coupled with a state-of-the-art CPU, the entire touchscreen sensing solution can measure, classify and track a number of individual finger touches with a high degree of accuracy in the shortest response time.
- **Capacitive Touch Engine (CTE)** – The mXT336UD-MAU002 features an acquisition engine that uses an optimal measurement approach to ensure almost complete immunity from parasitic capacitance on the receiver input lines. The engine includes sufficient dynamic range to cope with anticipated touchscreen self and mutual capacitances, which allows great flexibility for use with the Microchip proprietary sensor pattern designs. One- and two-layer ITO sensors are possible using glass or PET substrates.
- **Touch detection** – The mXT336UD-MAU002 allows for both mutual and self capacitance measurements, with the self capacitance measurements being used to augment the mutual capacitance measurements to produce reliable touch information.

  When self capacitance measurements are enabled, touch classification is achieved using both mutual and self capacitance touch data. This has the advantage that both types of measurement systems can work together to detect touches under a wide variety of circumstances.

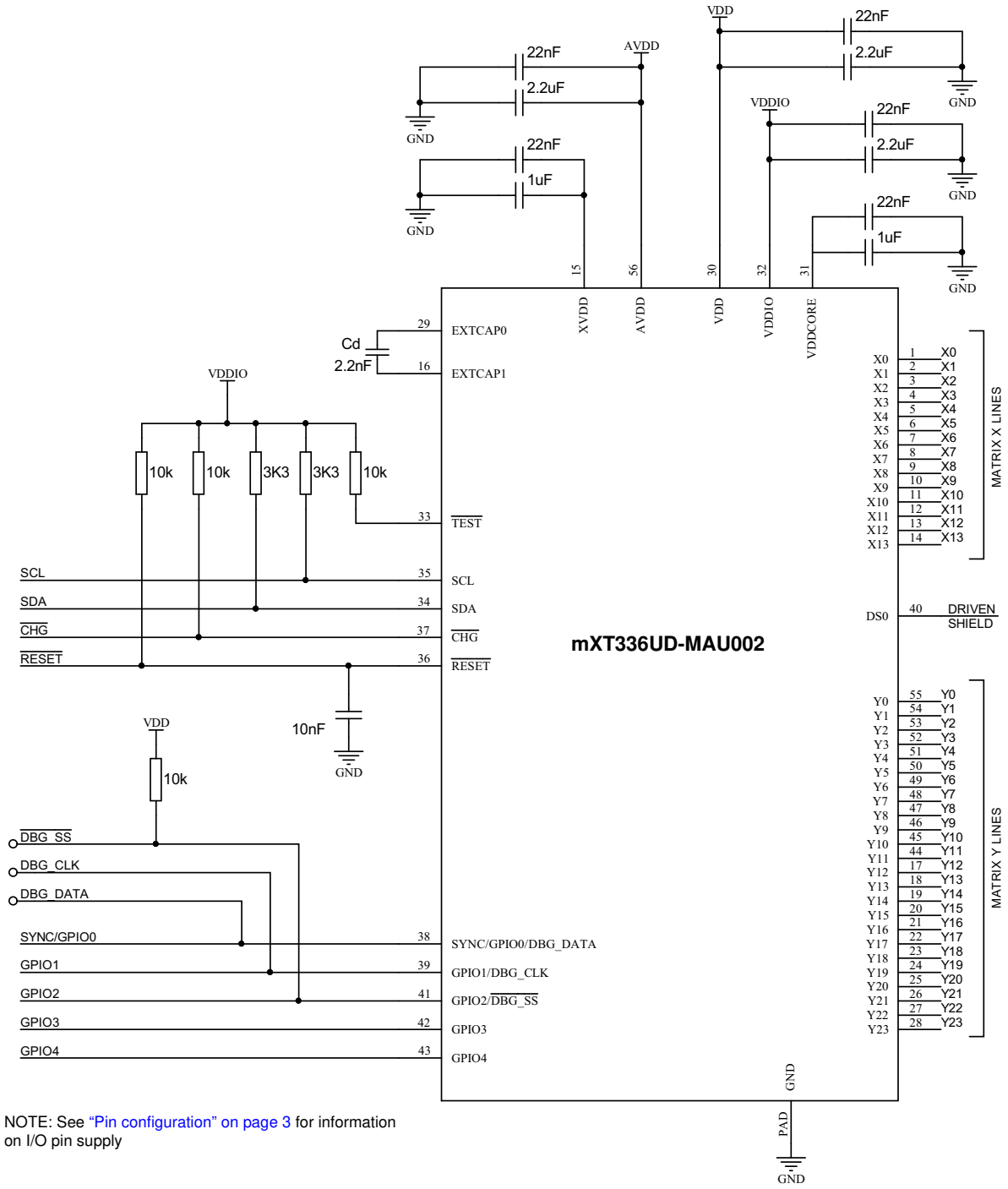
  The system may be configured for different types of default measurements in both idle and active modes. For example, the device may be configured for Mutual Capacitance Touch as the default in active mode and Self Capacitance Touch as the default in idle mode. Note that other types of scans (such as P2P mutual capacitance scans and other types of self capacitance scans) may also be made depending on configuration.

  Mutual capacitance touch data is used wherever possible to classify touches as this has a greater resolution than self capacitance measurements and provides positional information on touches. For this reason, multiple touches can only be determined by mutual capacitance touch data. In Self Capacitance Touch Default mode, if the self capacitance touch processing detects multiple touches, touchscreen processing is skipped until mutual capacitance touch data is available.

  Self capacitance and P2P mutual capacitance measurements allow for the detection of touches in extreme scenarios, such as thick glove touches, when mutual capacitance touch detection alone may miss touches.
- **Display Noise Cancellation** – A combination of analog circuitry, hardware noise processing, and firmware combats display noise without requiring additional listening channels or synchronization to display timing. This enables the use of shieldless touch sensor stacks, including touch-on-lens.
- **Noise filtering** – Hardware noise processing in the capacitive touch engine provides enhanced autonomous filtering and allows a broad range of noise profiles to be handled. The result is good performance in the presence of LCD noise.
- **Processing power** – The main CPU has two companion microsequencer coprocessors under its control consuming low power. This system allows the signal acquisition, preprocessing and postprocessing to be partitioned in an efficient and flexible way.
- **Interpreting user intention** – The Microchip hybrid mutual and self capacitance method provides unambiguous multitouch performance. Algorithms in the mXT336UD-MAU002 provide optimized touchscreen position filtering for the smooth tracking of touches, responding to a user's intended touches while preventing false touches triggered by ambient noise, conductive material on the sensor surface, such as moisture, or unintentional touches from the user's resting palm or fingers.

2.0 SCHEMATIC

2.1 Schematic XQFN 56 Pins



NOTE: See "Pin configuration" on page 3 for information on I/O pin supply

See Section 2.2 "Schematic Notes"

2.2 Schematic Notes

2.2.1 POWER SUPPLY

The sense and I/O pins are supplied by the power rails on the device as listed in Table 2-1. This information is also indicated in "Pin configuration" on page 3.

TABLE 2-1: POWER SUPPLY FOR SENSE AND I/O PINS

Power Supply	Pins
XVdd	X sense pins
AVdd	Y sense pins
Vdd	GPIO2, GPIO3/$\overline{\text{DBG\_SS}}$, GPIO4
VddIO	$\overline{\text{RESET}}$, $\overline{\text{TEST}}$, $\overline{\text{CHG}}$ SCL, SDA, SYNC/GPIO0/DBG_DATA, GPIO1/DBG_CLK

2.2.2 DECOUPLING CAPACITORS

All decoupling capacitors must be X7R or X5R and placed less than 5 mm away from the pins for which they act as bypass capacitors. Pins of the same type can share a capacitor provided no pin is more than 10 mm from the capacitor.

The schematics on the previous pages show the capacitors required. The parallel combination of capacitors is recommended to give high and low frequency filtering, which is beneficial if the voltage regulators are likely to be some distance from the device (for example, if an active tail design is used). Note that this requires that the voltage regulator supplies for AVdd, Vdd and VddIO are clean and noise free. It also assumes that the track length between the capacitors and on-board power supplies is less than 50 mm.

The number of base capacitors can be reduced if the pinout configuration means that sharing a bypass capacitor is possible (subject to the distance between the pins satisfying the conditions above and there being no routing difficulties).

2.2.3 PULL-UP RESISTORS

The pull-up resistors shown in the schematic are suggested typical values and may be modified to meet the requirements of an individual customer design.

This applies, in particular, to the pull-up resistors on the I^2C SDA and SCL lines (shown on the schematic), as the values of these resistors depend on the speed of the I^2C interface. See Section 11.9 "I2C Specification" for details.

Note that if a VddIO supply at the low end of the allowable range is used, the I^2C pull-up resistor values may need to be reduced.

2.2.4 VDDCORE

VddCore is internally generated from the Vdd power supply. To guarantee stability of the internal voltage regulator, one or more external decoupling capacitors are required.

2.2.5 XVDD

XVdd power can be supplied either as high voltage (using an internal voltage pump) or as low voltage (connected directly to the AVdd supply). The operating mode should be chosen according to the final application.

The voltage pump requires one external capacitor:

- EXTCAP0 must be connected to EXTCAP1 via a capacitor (Cd).
- The capacitor on XVDD should be rated at least 10 V if the voltage doubler is used.

Capacitor Cd should provide a capacitance of 2.2 nF. The capacitor must be placed as close as possible to the EXTCAP*n* pins.

If low voltage XVdd is required (that is, the XVdd voltage doubler is not required):

- Capacitor Cd must be omitted and EXTCAP0 and EXTCAP1 left unconnected.
- XVDD must be connected directly to the AVdd supply.

CAUTION! The device may be permanently damaged if the XVDD supply pin is shorted to Ground or high current is drawn from it.

2.2.6 AVDD

A diode from AVDD to VDD is present in the device. If AVDD and VDD are driven from different supplies, the Vdd supply must be powered up earlier than AVdd.

2.2.7 DRIVEN SHIELD LINE

The driven shield line (DS0) should be used to shield the X/Y sense lines. Specifically, it acts as a driven shield in self capacitance operation. See Section 8.4 “Driven Shield Line” for more details.

2.2.8 MULTIPLE FUNCTION PINS

Some pins may have multiple functions. In this case, only one function can be chosen and the circuit should be designed accordingly.

2.2.9 SYNC PIN

The mXT336UD-MAU002 has a single SYNC pin that can be used for either frame synchronization (typically connected to VSYNC) or pulse synchronization (typically connected to HSYNC), but not both.

2.2.10 GPIO PINS

The mXT336UD-MAU002 has 5 GPIO pins. The pins can be set to be either an input or an output, as required, using the GPIO Configuration T19 object.

If a GPIO pin is unused, it should be handled as identified in “Pin configuration” on page 3. The pin should also be given a defined state by the GPIO Configuration T19 object.

By default, the GPIO pins are set to be inputs so if a pin is not used, and is left configured as an input, it should be connected to GND through a resistor. Alternatively, the internal pull-up resistor should be enabled (in the GPIO Configuration T19 object) to pull up the pin. Note that this does not apply if the GPIO pin is shared with a debug line; see Section 2.2.11 “SPI Debug Interface” for advice on how to treat an unused GPIO pin in this case.

Alternatively, the GPIO pin can be set as an output low using the GPIO Configuration T19 object and left open. This second option avoids any problems should the pin accidentally be configured as output high at a later date.

If the GPIO Configuration T19 object is not enabled for use, the GPIO pins cannot be used for GPIO purposes, although any alternative function can still be used.

Some GPIO pins have alternative functions or other restrictions. In particular, if an alternative function is used then this takes precedence over the GPIO function, and the pin cannot be used as a GPIO pin. Note the following restrictions:

- GPIO0 cannot be used if the SYNC function is in use.
- The SPI Debug Interface functionality is shared with some of the GPIO pins. See Section 2.2.11 “SPI Debug Interface” for more details on the SPI Debug Interface and how to handle these pins if they are totally unused.

2.2.11 SPI DEBUG INTERFACE

The DBG_CLK, DBG_DATA and $\overline{\text{DBG\_SS}}$ lines form the SPI Debug Interface. These pins should be routed to test points on all designs, such that they can be connected to external hardware during system development and for debug purposes. See also Section 10.1 “SPI Debug Interface”.

The debug lines may share pins with other functionality. If the circuit is designed to use the SPI Debug Interface, then any alternative functionality cannot be used. Specifically:

- The DBG_CLK line shares functionality with GPIO1; therefore GPIO1 cannot be used if the SPI Debug Interface is in use.
- The DBG_DATA line shares functionality with GPIO0; therefore GPIO0 cannot be used if the SPI Debug Interface is in use.
- The $\overline{\text{DBG\_SS}}$ line shares functionality with GPIO2; therefore GPIO2 cannot be used if the $\overline{\text{DBG\_SS}}$ line is in use.
- The pull-up resistor for $\overline{\text{DBG\_SS}}$ in the schematics is optional and should be present only if the line is used as $\overline{\text{DBG\_SS}}$.

The DBG_CLK, DBG_DATA and $\overline{\text{DBG\_SS}}$ lines should not be connected to power or GND. For this reason, where these pins are shared with GPIO pins and they are totally unused (that is, they are not being used as debug or GPIO pins), they should be set as outputs using the GPIO Configuration T19 object.

3.0 TOUCHSCREEN BASICS

3.1 Sensor Construction

A touchscreen is usually constructed from a number of transparent electrodes. These are typically on a glass or plastic substrate. They can also be made using non-transparent electrodes, such as copper or carbon. Electrodes are constructed from Indium Tin Oxide (ITO) or metal mesh. Thicker electrodes yield lower levels of resistance (perhaps tens to hundreds of Ω/square) at the expense of reduced optical clarity. Lower levels of resistance are generally more compatible with capacitive sensing. Thinner electrodes lead to higher levels of resistance (perhaps hundreds of Ω/square) with some of the best optical characteristics.

Interconnecting tracks in ITO can cause problems. The excessive RC time constants formed between the resistance of the track and the capacitance of the electrode to ground can inhibit the capacitive sensing function. In such cases, the tracks should be replaced by screen printed conductive inks (non-transparent) outside the touchscreen viewing area.

3.2 Electrode Configuration

The specific electrode designs used in Microchip touchscreens are the subject of various patents and patent applications. Further information is available on request.

The device supports various configurations of electrodes as summarized in Section 4.0 “Sensor Layout”.

3.3 Scanning Sequence

All nodes are scanned in sequence by the device. Where possible, there is a parallelism in the scanning sequence to improve overall response time. The nodes are scanned by measuring capacitive changes at the intersections formed between the first drive (X) line and all the receive (Y) lines. Then the intersections between the next drive line and all the receive lines are scanned, and so on, until all X and Y combinations have been measured.

The device can be configured in various ways. It is possible to disable some nodes so that they are not scanned at all. This can be used to improve overall scanning time.

3.4 Touchscreen Sensitivity

3.4.1 ADJUSTMENT

Sensitivity of touchscreens can vary across the extents of the electrode pattern due to natural differences in the parasitic capacitance of the interconnections, control chip, and so on. An important factor in the uniformity of sensitivity is the electrode design itself. It is a natural consequence of a touchscreen pattern that the edges form a discontinuity and hence tend to have a different sensitivity. The electrodes at the edges do not have a neighboring electrode on one side and this affects the electric field distribution in that region.

A sensitivity adjustment is available for the whole touchscreen. This adjustment is a basic algorithmic threshold that defines when a node is considered to have enough signal change to qualify as being in detect.

3.4.2 MECHANICAL STACKUP

The mechanical stackup refers to the arrangement of material layers that exist above and below a touchscreen. The arrangement of the touchscreen in relation to other parts of the mechanical stackup has an effect on the overall sensitivity of the screen. The maXTouch technology has an excellent ability to operate in the presence of ground planes close to the sensor. The sensitivity of the maXTouch technology is attributed more to the interaction of the electric fields between the transmitting (X) and receiving (Y) electrodes than to the surface area of these electrodes. For this reason, stray capacitance on the X or Y electrodes does not strongly reduce sensitivity.

Front panel dielectric material has a direct bearing on sensitivity. Plastic front panels are usually suitable up to about 5 mm, and glass up to about 10 mm (dependent upon the screen size and layout). The thicker the front panel, the lower the signal-to-noise ratio of the measured capacitive changes and hence the lower the resolution of the touchscreen. In general, glass front panels are near optimal because they conduct electric fields almost twice as easily as plastic panels.

NOTE	Care should be taken using ultra-thin glass panels as retransmission effects can occur, which can significantly degrade performance.

4.0 SENSOR LAYOUT

NOTE	The specific electrode designs used in Microchip touchscreens may be the subject of various patents and patent applications. Further information is available on request.

4.1 Electrodes

The device supports various configurations of touch electrodes as summarized below:

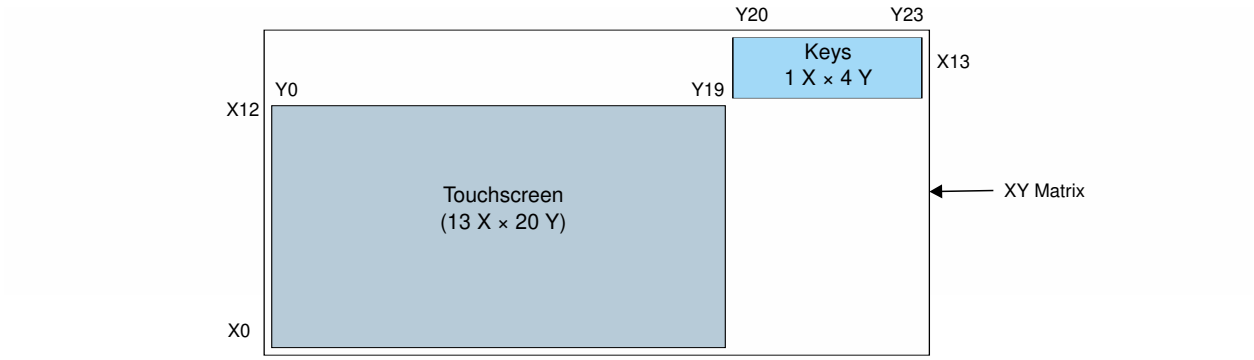
- Touchscreen: 1 touchscreen panel occupies a rectangular matrix of up to 14 X × 24 Y lines maximum (subject to other configurations).
- Keys: Up to 16 keys in an X/Y grid (Key Array), with each node (X/Y intersection) forming a key within the array.

The physical sensor matrix is configured using one or more touch objects. It is not mandatory to have all the allowable touch objects on the device enabled, nor is it mandatory to use all the rows and columns on the matrix, so objects that are not required can be left disabled (default).

4.2 Sensor Matrix Layout

An example layout is shown in Figure 4-1.

FIGURE 4-1: EXAMPLE LAYOUT



When designing the physical layout of the touch panel, the following rules must be obeyed:

- **General layout rules:**
  - Each touch object should be a regular rectangular shape in terms of the lines it uses.
  - Although each touch object must use a contiguous block of X or Y lines, there can be gaps between the blocks of X and Y lines used for the different touch objects
- **Additional layout rules for Multiple Touch Touchscreen T100:**
  - The Multiple Touch Touchscreen T100 object ***must*** start at (X0, Y0)
  - The Multiple Touch Touchscreen T100 object cannot share an X or Y line with another touch object (for example, a Key Array T15) if self capacitance measurements are enabled. Note that sharing of X or Y lines is allowed for mutual capacitance only designs, but this is not recommended for compatibility reasons.
  - The touchscreen must contain a minimum of 3 X lines. If Dual X Drive is enabled for use in the Noise Suppression T72 object, the minimum is 4 X lines.
  - The touchscreen must contain a minimum of 3 Y lines.
  - Self Capacitance touchscreens must have an even number of Y lines if low frequency compensation is used.
- **Additional layout rules for Key Array T15:**
  - The Key Array must occupy higher X and Y lines than those used by the Multiple Touch Touchscreen T100 object.

4.3 Permitted Configurations

The permitted X/Y configurations are shown in Table 4-1.

TABLE 4-1: PERMITTED TOUCHSCREEN CONFIGURATIONS

Number of X Lines \ Number of Y Lines	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1
14	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	M	M		
13	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	M	M		
12	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	M	M		
11	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	M	M		
10	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	M	M		
9	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	M	M		
8	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	M	M		
7	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	M	M		
6	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	Y	Y	M	M	M	M		
5	P	P	M	M	P	P	M	M	P	P	M	M	P	P	M	M	P	P	M	M	M	M		
4	P	P	M	M	P	P	M	M	P	P	M	M	P	P	M	M	P	P	M	M	M	M		
3	X	X	Z	Z	X	X	Z	Z	X	X	Z	Z	X	X	Z	Z	X	X	Z	Z	Z	Z		
2																								
1																								

Key:

- Y — Configuration supported for self capacitance and all mutual capacitance measurements; configuration recommended
- P — Configuration supported for all mutual capacitance measurement types; self capacitance measurements not supported
- M — Configuration supported for non P2P mutual capacitance measurements only; self capacitance measurements not supported
- X — Configuration supported for all mutual capacitance measurements types, but only if dual X is *not* used; self capacitance measurements not supported
- Z — Configuration supported for non P2P mutual capacitance measurements, but only if dual X is *not* used; self capacitance measurements not supported
- Configuration not supported

4.4 Touchscreen Size

Table 4-2 lists some typical screen size and electrode pitch combinations to achieve various touchscreen aspect ratios.

TABLE 4-2: TYPICAL SCREEN SIZES

Aspect Ratio	Matrix Size	Node Count	Screen Diagonal (Inches)			
			3.8 mm Pitch (2)	4.5 mm Pitch	5.5 mm Pitch	6.5 mm Pitch
Single Touchscreen (1)						
16:10	X = 14, Y = 23	322	4.0	4.8	5.8	6.9
16:9	X = 14, Y = 24	336	4.2	4.9	6.0	7.1
4:3	X = 14, Y = 19	266	3.5	4.2	5.1	6.0
2:1	X = 12, Y = 24	288	4.0	4.8	5.8	6.9

Note 1: The figures given in the table are for a Touchscreen and show the largest node count possible to achieve the desired aspect ratio. No provision has been made for a Key Array.

2: Recommended sensor pitch for 1.5 mm passive stylus tip diameter.

4.5 Driven Shield Line

The driven shield line (DS0) should be used to shield the X/Y sense lines. See Section 8.4 “Driven Shield Line” for more details.

5.0 POWER-UP / RESET REQUIREMENTS

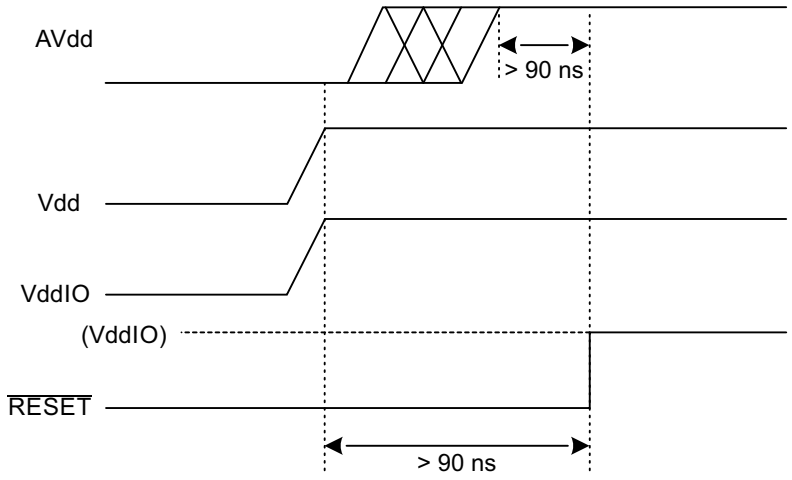
5.1 Power-on Reset

There is an internal Power-on Reset (POR) in the device.

If an external reset is to be used the device must be held in $\overline{\text{RESET}}$ (active low) while the digital (Vdd), analog (AVdd) and digital I/O (VddIO) power supplies are powering up. The supplies must have reached their nominal values before the $\overline{\text{RESET}}$ signal is deasserted (that is, goes high). This is shown in Figure 5-1. See Section 11.2 “Recommended Operating Conditions” for nominal values for the power supplies to the device.

A diode from AVDD to VDD is present in the device. If AVDD and VDD are driven from different supplies, the Vdd supply must be powered up earlier than AVdd.

FIGURE 5-1: POWER SEQUENCING ON THE MXT336UD-MAU002



Note: When using external $\overline{\text{RESET}}$ at power-up, VddIO must not be enabled after Vdd

It is recommended that customer designs include the capability for the host to control all the maXTouch power supplies and pull the $\overline{\text{RESET}}$ line low.

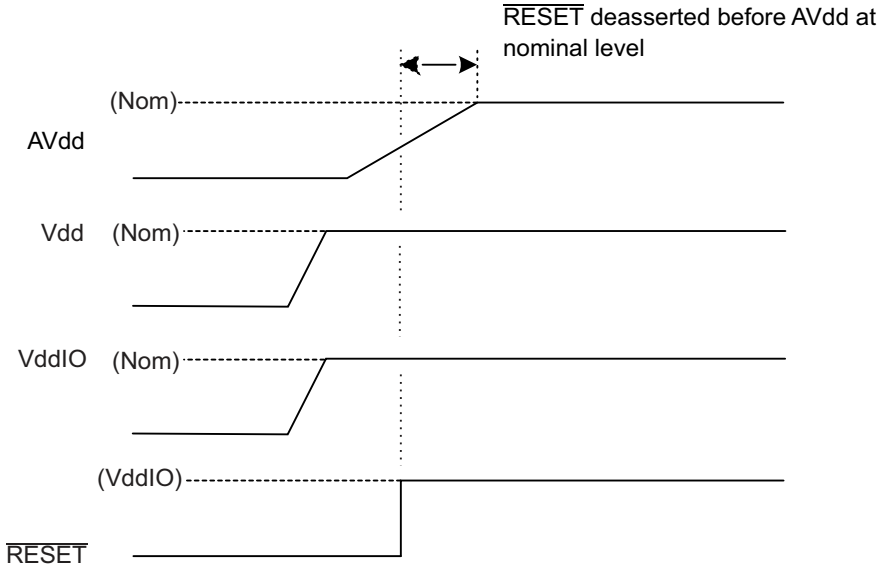
After power-up, the device typically takes 48 ms to 70 ms before it is ready to start communications, depending on the configuration.

NOTE	Device initialization will not complete until after all the power supplies are present. If any power supply is not present, internal initialization stalls and the device will not communicate with the host.

If the $\overline{\text{RESET}}$ line is released before the AVdd supply has reached its nominal voltage (see Figure 5-2), then some additional operations need to be carried out by the host. There are two options open to the host controller:

- Start the part in Deep Sleep mode and then send the command sequence to set the cycle time to wake the part and allow it to run normally. Note that in this case a calibration command is also needed.
- Send a RESET command.

FIGURE 5-2: POWER SEQUENCING ON THE MXT336UD-MAU002 – LATE RISE ON AVDD



5.2 Hardware Reset

The RESET pin can be used to reset the device whenever necessary. The RESET pin must be asserted low for at least 90 ns to cause a reset. After the host has released the RESET pin, the device typically takes 47 ms to 70 ms before it is ready to start communications, depending on the configuration. It is recommended to connect the RESET pin to a host controller to allow the host to initiate a full hardware reset without requiring the mXT336UD-MAU002 to be powered down.

WARNING	The device should be reset only by using the RESET line. If an attempt is made to reset by removing the power from the device without also sending the signal lines low, power will be drawn from the communication and I/O lines and the device will not reset correctly.

Make sure that any lines connected to the device are below or equal to Vdd during power-up and power-down. For example, if RESET is supplied from a different power domain to the VDDIO pin, make sure that it is held low when Vdd is off. If this is not done, the RESET signal could parasitically couple power via the RESET pin into the Vdd supply.

NOTE	The voltage level on the RESET pin of the device must never exceed VddIO (digital supply voltage).

5.3 Software Reset

A software RESET command (using the Command Processor T6 object) can be used to reset the chip. A software reset typically takes 69 ms to 90 ms before it is ready to start communications, depending on the configuration.

The reset flag is set in the Command Processor T6 object message data to indicate to the host that it has just completed a reset cycle. This bit can be used by the host to detect any unexpected brownout events. This allows the host to take any necessary corrective actions, such as reconfiguration.

5.4 CHG Line

After the device has reset, it asserts the CHG line to signal to the host that a message is available.

NOTE	The CHG line is briefly set (~100 ms) as an input during power-up or reset. It is therefore particularly important that the line should be allowed to float high via the CHG line pull-up resistor during this period: it should never be driven by the host (see Section 11.5.3 “Reset Timings”).

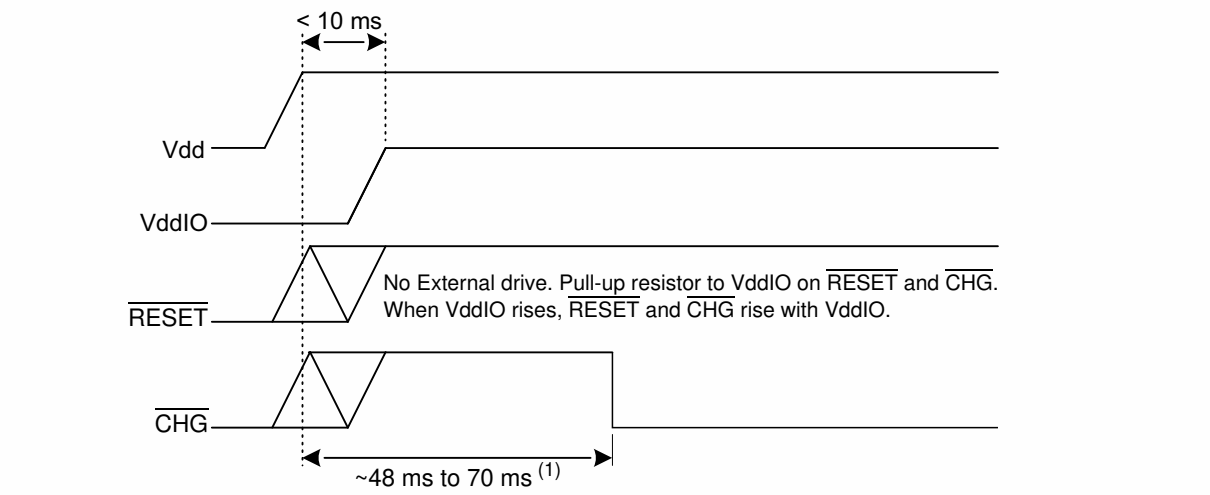
At power-on, the device can be configured to perform self tests (using the Self Test Control T10 object) to check for faults in the device.

5.5 Power-up and Reset Sequence – VddIO Enabled after Vdd

The power-up sequence that can be used in applications where VddIO must be powered up after Vdd, is shown in Figure 5-3.

In this case the communication interface to the maXTouch device is not driven by the host system. The $\overline{\text{RESET}}$ and $\overline{\text{CHG}}$ lines are connected to VddIO using suitable pull-up resistors. Vdd is powered up, followed by VddIO, no more than 10 ms after Vdd. Due to the pull-up resistors, $\overline{\text{RESET}}$ and $\overline{\text{CHG}}$ lines will rise with VddIO. The internal POR system ensures reliable boot up of the device and the $\overline{\text{CHG}}$ line will go low approximately 48 ms to 70 ms (depending on the configuration) after Vdd to notify the host that the device is ready to start communication.

FIGURE 5-3: POWER-UP SEQUENCE



Note 1: Depends on configuration

6.0 DETAILED OPERATION

6.1 Touch Detection

The mXT336UD-MAU002 allows for both mutual and self capacitance measurements, with the self capacitance measurements being used to augment the mutual capacitance measurements to produce reliable touch information.

When self capacitance measurements are enabled, touch classification is achieved using both mutual and self capacitance touch data. This has the advantage that both types of measurement systems can work together to detect touches under a wide variety of circumstances.

Mutual capacitance touch data is used wherever possible to classify touches as this has greater granularity than self capacitance measurements and provides positional information on touches.

Self capacitance measurements, on the other hand, allow for the detection of single touches in extreme cases, such as single thick glove touches, when touches can only be detected by self capacitance data and may be missed by mutual capacitance touch detection.

6.2 Operational Modes

The device operates in two modes: **Active** (touch detected) and **Idle** (no touches detected). Both modes operate as a series of burst cycles. Each cycle consists of a short burst (during which measurements are taken) followed by an inactive sleep period. The difference between these modes is the length of the cycles. Those in idle mode typically have longer sleep periods. The cycle length is configured using the IDLEACQINT and ACTVACQINT settings in the Power Configuration T7. In addition, an *Active to Idle Timeout* setting is provided.

6.3 Detection Integrator

The device features a touch detection integration mechanism. This acts to confirm a detection in a robust fashion. A counter is incremented each time a touch has exceeded its threshold and has remained above the threshold for the current acquisition. When this counter reaches a preset limit the sensor is finally declared to be touched. If, on any acquisition, the signal is not seen to exceed the threshold level, the counter is cleared and the process has to start from the beginning.

The detection integrator is configured using the appropriate touch objects (Multiple Touch Touchscreen T100, Key Array T15).

6.4 Sensor Acquisition

The charge time for mutual capacitance measurements is set using the Acquisition Configuration T8 object. The device combines a number of factors together to arrive at the total acquisition time for one drive line (that is, one X line for mutual capacitance acquisitions or one axis for self capacitance acquisitions).

The following constraints apply on the mXT336UD-MAU002:

- The per X line mutual capacitance touch measurement and the per axis self capacitance measurement should not exceed 2 ms. Furthermore, the total acquisition time for the sensor as a whole must not exceed 250 ms. In the event of a timeout, a SIGERR may be reported.
- The high and low pulse periods must not exceed 51.26 µs each. This means that the maximum possible burst period is 102.46 µs (that is, a minimum frequency of 9.76 kHz). In addition, the burst period must not be less than 4 µs (that is, a maximum frequency of 250 kHz).

Unpredictable system behavior might occur if any of the above constraints are not met.

Care should be taken to configure all the objects that can affect the measurement timing (for example, drift and noise measurement interval settings) so that these limits are not exceeded.

6.5 Calibration

Calibration is the process by which a sensor chip assesses the background capacitance on each node. Calibration occurs in a variety of circumstances, for example:

- When determined by the mutual capacitance recalibration process, as controlled by the Acquisition Configuration T8 object
- When determined by the self capacitance recalibration process, as controlled by the Self Capacitance Configuration T111 object
- When the Retransmission Compensation T80 object detects calibrated-in moisture has been removed
- Following a Self Capacitance Global Configuration T109 Tune command
- When the host issues a recalibrate command
- When certain configuration settings are changed

6.6 Digital Filtering and Noise Suppression

The mXT336UD-MAU002 supports on-chip filtering of the acquisition data received from the sensor. Specifically, the Noise Suppression T72 object provides an algorithm to suppress the effects of noise (for example, from a noisy charger plugged into the user's product). This algorithm can automatically adjust some of the acquisition parameters during operation to filter the Analog-to-Digital Conversions (ADCs) received from the sensor.

Additional noise suppression is provided by the Self Capacitance Noise Suppression T108 object. Similar in both design and configuration to the Noise Suppression T72 object, the Self Capacitance Noise Suppression T108 object is the noise suppression interface for self capacitance touch measurements.

Noise suppression is triggered when a noise source is detected.

- The host driver code can indicate when a noise source is present.
- The noise suppression is also triggered based on the noise levels detected using internal line measurements.The Noise Suppression T72 and Self Capacitance Noise Suppression T108 object selects the appropriate controls to suppress the noise present in the system.

6.7 EMC Reduction

The mXT336UD-MAU002 has the following mechanisms to help reduce EMC emissions and ensure that the user's product operates within the desired EMC limits:

- **Configurable Voltage Reference Mode** – Allows for the selection of voltage swing of the self capacitance measurements.This feature is configured by the Self Capacitance Global Configuration T109 object.
- **Input Buffer Power Configuration** – Controls the positive/negative drive strength of the Input Buffer for self capacitance measurements. This feature is configured by the Self Capacitance Global Configuration T109 object.
- **Configurable Input Amplifier Bias** – Controls the Input Amplifier Bias. This feature is configured by the Self Capacitance Global Configuration T109 object.

6.8 Shieldless Support and Display Noise Suppression

The mXT336UD-MAU002 can support shieldless sensor design even with a noisy LCD.

The Optimal Integration feature is not filtering as such, but enables the user to use a shorter integration window. The integration window optimizes the amount of charge collected against the amount of noise collected, to ensure an optimal SNR. This feature also benefits the system in the presence of an external noise source. This feature is configured using the Shieldless T56 object.

Display noise suppression allows the device to overcome display noise simultaneously with external noise. This feature is based on filtering provided by the Lens Bending T65 object (see Section 6.11 "Lens Bending").

6.9 Retransmission Compensation

The device can limit the undesirable effects on the mutual capacitance touch signals caused by poor device coupling to ground, such as poor sensitivity and touch break-up. This is achieved using the Retransmission Compensation T80 object. This object can be configured to allow the touchscreen to compensate for signal degradation due to these undesirable effects. If self capacitance measurements are also scheduled, the Retransmission Compensation T80 object will use the resultant data to enhance the compensation process.

The Retransmission Compensation T80 object is also capable of compensating for water presence on the sensor if self capacitance measurements are scheduled. In this case, both mutual capacitance and self capacitance measurements are used to detect moisture and then, once moisture is detected, self capacitance measurements are used to detect single touches in the presence of moisture.

6.10 Grip Suppression

The device has grip suppression functionality to suppress false detections from a user's grip.

Grip suppression works by specifying a boundary around a touchscreen, within which touches can be suppressed whilst still allowing touches in the center of the touchscreen. This ensures that an accidental hand touch on the edge is suppressed while still allowing a "real" (finger) touch towards the center of the screen. Mutual capacitance grip suppression is configured using the Grip Suppression T40 object.

6.11 Lens Bending

The device supports algorithms to eliminate disturbances from the measured signal.

When the sensor suffers from the screen deformation (lens bending) the signal values acquired by normal procedure are corrupted by the disturbance component (bend). The amount of bend depends on:

- The mechanical and electrical characteristics of the sensor
- The amount and location of the force applied by the user touch to the sensor
- The Lens Bending T65 object measures the bend component and compensates for any distortion caused by the bend. As the bend component is primarily influenced by the user touch force, it can be used as a secondary source to identify the presence of a touch. The additional benefit of the Lens Bending T65 object is that it will eliminate LCD noise as well.

6.12 Glove Detection

The device has glove detection algorithms that process the measurement data received from the touchscreen classifying touches as potential gloved touches.

The Glove Detection T78 object is used to detect glove touches. In Normal Mode the Glove Detection T78 object applies vigorous glove classification to small signal touches to minimize the effect of unintentional hovering finger reporting. Once a gloved touch is found, the Glove Detection T78 object can enter Glove Confidence Mode. In this mode the device expects the user to be wearing gloves so the classification process is much less stringent.

6.13 Stylus Support

The mXT336UD-MAU002 allows for the particular characteristics of passive stylus touches, whilst still allowing conventional finger touches to be detected. The touch sensitivity and threshold controls for stylus touches are configured separately from those for conventional finger touches so that both types of touches can be accommodated.

Stylus support ensures that the small touch area of a stylus registers as a touch, as this would otherwise be considered too small for the touchscreen. Additionally, there are controls to distinguish a stylus touch from an unwanted approaching finger (such as on the hand holding the stylus).

Passive stylus touches are configured by the Passive Stylus T47 object. There is one instance of the Passive Stylus T47 object for each Multiple Touch Touchscreen T100 object present on the device.

6.14 Unintentional Touch Suppression

The Touch Suppression T42 object provides a mechanism to suppress false detections from unintentional touches from a large body area, such as from a palm. The Touch Suppression T42 object also provides Maximum Touch Suppression to suppress all touches if more than a specified number of touches has been detected.

6.15 Adjacent Key Suppression Technology

Adjacent Key Suppression (AKS) technology is a patented method used to detect which touch object (Multiple Touch Touchscreen T100 or Key Array T15) is touched, and to suppress touches on the other touch objects, when touch objects are located close together.

The device has two levels of AKS:

- The first level works between the touch objects (Multiple Touch Touchscreen T100 and Key Array T15). The touch objects are assigned to AKS groups. If a touch occurs within one of the touch objects in a group, then touches within other objects inside that group are suppressed. For example, if a touchscreen and a Key Array are placed in the same AKS group, then a touch in the touchscreen will suppress touches in the Key Array, and vice versa. Objects can be in more than one AKS group.
- The second level of AKS is internal AKS within an individual Key Array object. If internal AKS is enabled, then when one key is touched, touches on all the other keys within the Key Array are suppressed. Note that internal AKS is not present on other types of touch objects.

6.16 Device Encryption

For added security, the mXT336UD-MAU002 allows for the encryption of important configuration parameters within the device, and for the encryption of messages sent by the device.

The default state of the mXT336UD-MAU002 is to be unencrypted, which allows the host to interact with the device using the standard Object-based Protocol in the same manner as any other unencrypted maXTouch device. However, the host can enable encryption if desired. This uses the AES 128 algorithm (Cipher Block Chaining mode) for the encryption and decryption of data. One or more of the following encryption modes are possible:

- Encrypted configuration read/write
- Encrypted Message Processor T5 messages

Encryption is requested by downloading the encryption parameters to the Serial Data Command T68 object. Encryption is then activated when the device is next reset. If the device has active encryption, the Variant ID is reported with bit 7 set to 1. This provides a method for the host controller to detect if encryption is in use.

The current encryption status can be read from the device using the Encryption Status T2 object.

7.0 I²C COMMUNICATIONS

Communication with the mXT336UD-MAU002 is carried out over the I²C interface.

The I²C interface is used in conjunction with the $\overline{\text{CHG}}$ line. The $\overline{\text{CHG}}$ line going active signifies that a new data packet is available. This provides an interrupt-style interface and allows the device to present data packets when internal changes have occurred. See Section 7.5 “CHG Line” for more information.

7.1 I²C Address

The mXT336UD-MAU002 supports one fixed I²C device address: 0x4A.

The I²C address is shifted left to form the SLA+W or SLA+R address when transmitted over the I²C interface, as shown in Table 7-1.

TABLE 7-1: FORMAT OF SLA+W/SLA+R

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Address: 0x4A							Read/write

7.2 Writing To the Device

An I²C WRITE cycle consists of the following bytes:

START	1 bit	I²C START condition
SLA+W	1 byte	I²C address of the device (see Section 7.1 “I2C Address”)
Address (LSByte, MSByte)	2 bytes	Address of the location at which the data writing starts. This address is stored as the address pointer.
Data Size (only if encryption is active)	2 bytes	If writing to an encrypted object, the size of the data to be written, including the data CRC (if requested). Otherwise these bytes must be set to zero. Note that these bytes will have a non-zero value only if writing one or more byes of data to an encrypted object. In all other cases the size should be set to zero (that is, when the object is not encrypted, or encryption is enabled for message reads only, or the data is zero bytes in length). **NOTE** These bytes are present only if encryption is active; they are not present if encryption is not active.
Data	0 or more bytes	The actual data to be written. The data is written to the device, starting at the location of the address pointer. The address pointer returns to its starting value when the I²C STOP condition is detected.
CRC (optional)	1 byte	An optional 8-bit CRC that includes all the bytes that have been sent, including the two address bytes and the data size bytes (if encryption is active), but not the SLA+W byte. If the device detects an error in the CRC during a write transfer, a COMSERR fault is reported by the Command Processor T6 object. See Section 7.3 “I²C Writes in Checksum Mode” for more details
Padding to 16 bytes (only if encrypted writes are enabled)	Maximum 15 bytes	If writing to an encrypted object, and there are one or more bytes of data (excluding the CRC), the data block (including the CRC, if present) must be padded to 16 bytes. **NOTE** If the data is zero bytes in size, the padding is not necessary and the data block will consist of the CRC only (if present).
STOP	1 bit	I²C STOP condition

Figure 7-1 and Figure 7-1 show examples of writing four bytes of data to contiguous addresses starting at 0x1234.

FIGURE 7-1: EXAMPLE OF A FOUR-BYTE WRITE – ENCRYPTION NOT ACTIVE

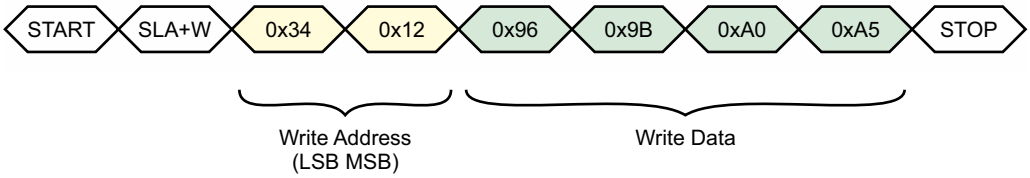
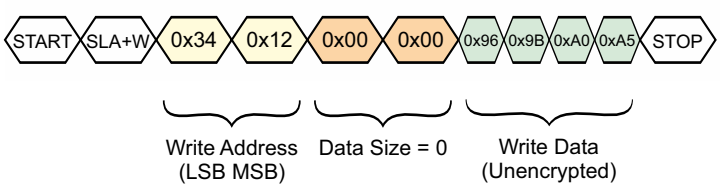
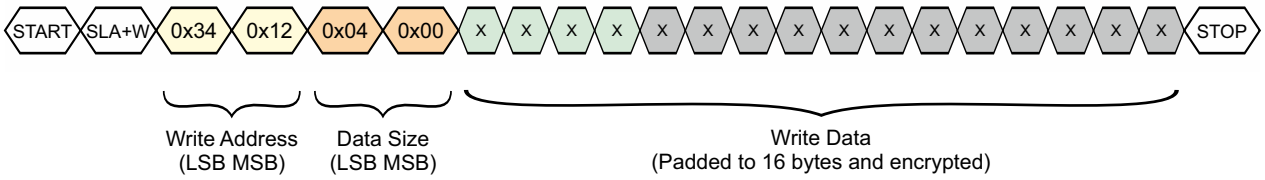


FIGURE 7-2: EXAMPLE OF A FOUR-BYTE WRITE – ENCRYPTION ACTIVE

Writing to an Unencrypted Object



Writing to an Encrypted Object



7.3 I²C Writes in Checksum Mode

In I²C checksum mode an 8-bit CRC is added to all I²C writes. The CRC is sent following the last data byte. All the bytes sent are included in the CRC, including the two address bytes and the two data size bytes (if encryption is active). Any command or data sent to the device is processed even if the CRC fails.

To indicate that a checksum is to be sent in the write, the most significant bit of the MSByte of the write address is set to 1. For example, the I²C command shown in Figure 7-3 writes a value of 150 (0x96) to address 0x1234 with a checksum. The address is changed to 0x**9**234 to indicate checksum mode.

FIGURE 7-3: EXAMPLE OF A WRITE TO ADDRESS 0x1234 WITH A CHECKSUM – ENCRYPTION NOT ACTIVE

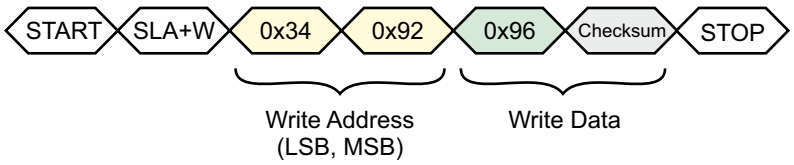
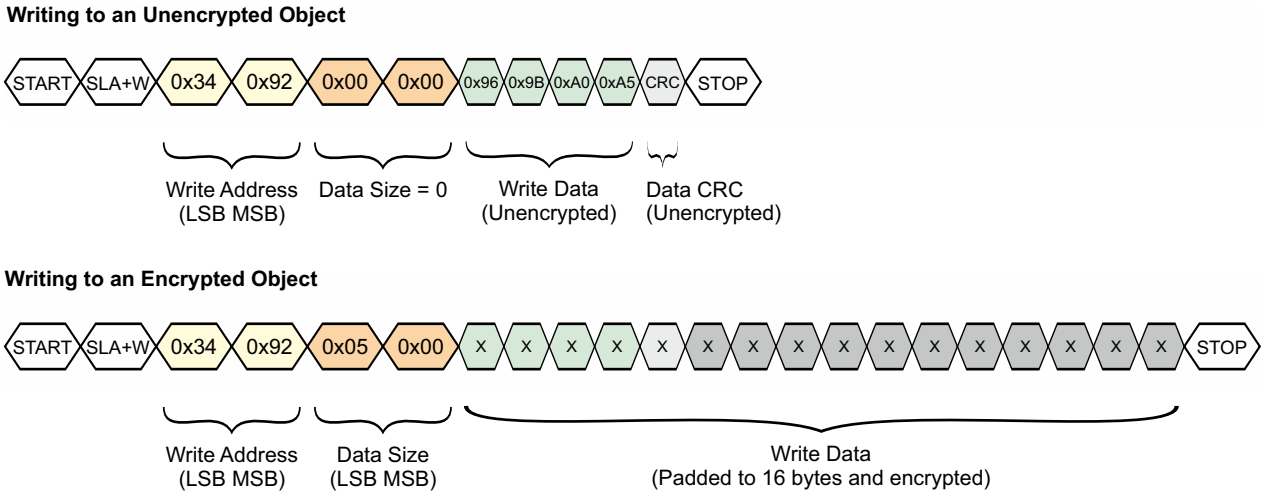


FIGURE 7-4: EXAMPLE OF A WRITE TO ADDRESS 0x1234 WITH A CHECKSUM – ENCRYPTION ACTIVE



7.4 Reading From the Device

Two I^2C bus activities must take place to read from the device. The first activity is an I^2C write to set the address pointer (LSByte then MSByte). The second activity is the actual I^2C read to receive the data. The address pointer returns to its starting value when the read cycle NACK or STOP is detected.

It is not necessary to set the address pointer before every read. The address pointer is updated automatically after every read operation. The address pointer will be correct if the reads occur in order. In particular, when reading multiple messages from the Message Processor T5 object, the address pointer is automatically reset to the address of the Message Processor T5 object, in order to allow continuous reads (see Section 7.4.2 “Reading Status Messages with DMA”).

NOTE	Encryption functionality on the mXT336UD-MAU002 means that if the host read request falls within the Message Processor T5 address space, but not at its start address, the device considers it a valid Message Processor T5 message read. The device therefore sends the entire Message Processor T5 message. Note that the message may be encrypted or unencrypted, depending on the message encryption setting.

The WRITE and READ cycles consist of a START condition followed by the I^2C address of the device (SLA+W or SLA+R respectively).

Figure 7-5 and Figure 7-6 show the I^2C commands to read four bytes starting at address 0x1234.

FIGURE 7-5: EXAMPLE OF A FOUR-BYTE READ – ENCRYPTION NOT ACTIVE

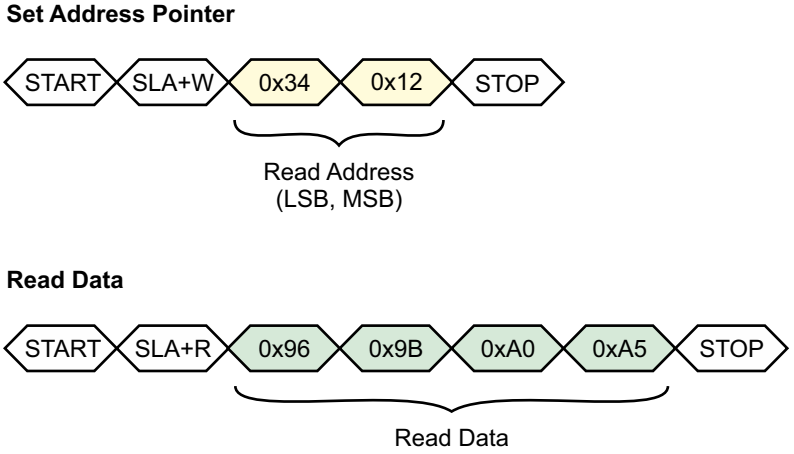
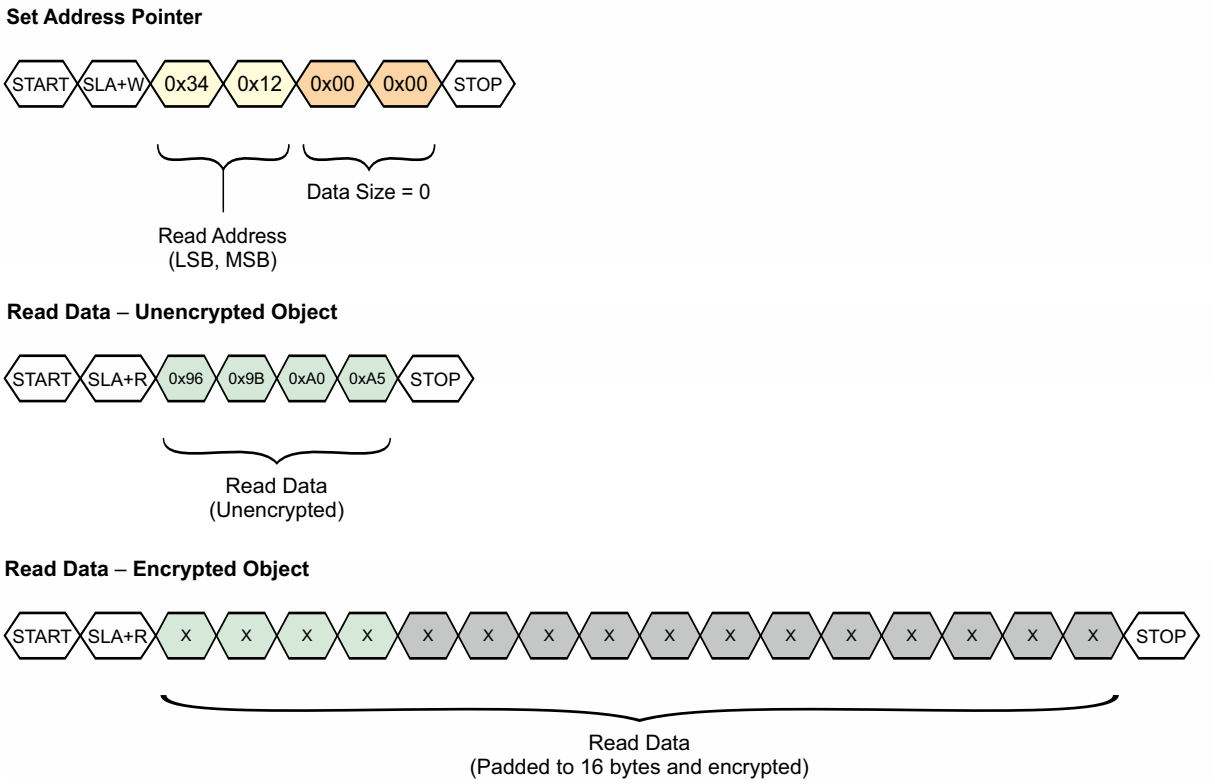


FIGURE 7-6: EXAMPLE OF A FOUR-BYTE READ – ENCRYPTION ACTIVE



NOTE	At least one data byte must be read during an I^2C READ transaction; it is illegal to abort the transaction with an I^2C STOP condition without reading any data.

7.4.1 READING A MESSAGE FROM THE MESSAGE PROCESSOR T5 OBJECT

An I^2C read of the Message Processor T5 object contains the following bytes:

START	1 bit	I^2C START condition
SLA+R	1 byte	I^2C address of the device (see Section 7.1 “I2C Address”)
Report ID	1 byte	Message report ID
Data	9 bytes	The message data (that is, the Message Processor T5 MESSAGE field)
CRC (optional)	1 byte	An 8-bit CRC (if requested) for the Message Processor T5 report ID and message data See Section 7.3 “I^2C Writes in Checksum Mode” for more details on how to request a checksum
Padding to 16 bytes (only if encrypted messages enabled)	5 or 6 bytes	If the encryption of Message Processor T5 messages is enabled, the data block (including the CRC, if present) is padded to 16 bytes.
STOP	1 bit	I^2C STOP condition

Figure 7-7 shows an example read from the Message Processor T5 object. To read multiple messages using Direct Memory Access, see Section 7.4.2 “Reading Status Messages with DMA”.

FIGURE 7-7: EXAMPLE READ FROM MESSAGE PROCESSOR T5 WITH A CHECKSUM – ENCRYPTION NOT ACTIVE

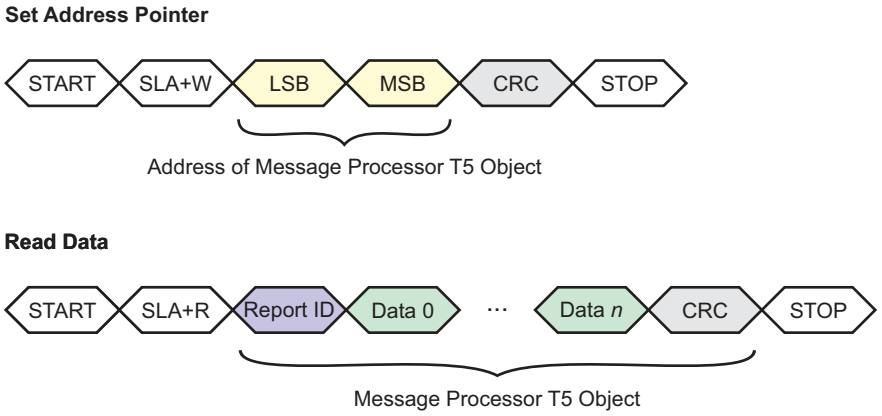
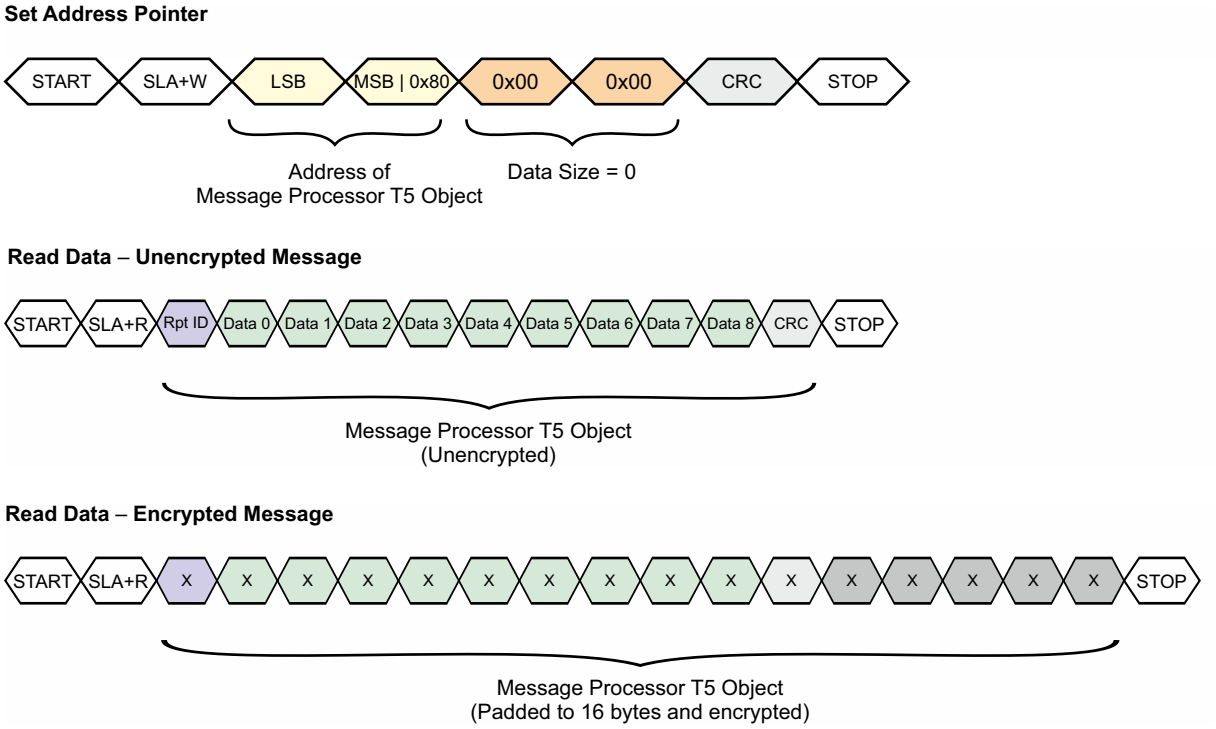


FIGURE 7-8: EXAMPLE READ FROM MESSAGE PROCESSOR T5 WITH A CHECKSUM – ENCRYPTION ACTIVE



7.4.2 READING STATUS MESSAGES WITH DMA

The device facilitates the easy reading of multiple messages using a single continuous read operation. This allows the host hardware to use a Direct Memory Access (DMA) controller for the fast reading of messages, as follows:

1. The host uses a write operation to set the address pointer to the start of the Message Count T44 object, if necessary. Note that the STOP condition at the end of the read resets the address pointer to its initial location, so it may already be pointing at the Message Count T44 object following a previous message read. If a checksum is required on each message, the most significant bit of the MSByte of the read address must be set to 1.
2. The host starts the read operation of the message by sending a START condition.
3. The host reads the Message Count T44 object (one byte) to retrieve a count of the pending messages.
4. The host calculates the number of bytes to read, as follows:
   - If encryption is not enabled, by multiplying the message count by the size of the Message Processor T5 object. Note that the host should have already read the size of the Message Processor T5 object in its initialization code.
   - If encryption is enabled, by multiplying the message count by 16. Note that, in order to decrypt the message data, the host will still need to know the size of the Message Processor T5 object.

   Note that the size of the Message Processor T5 object as recorded in the Object Table includes the checksum. If a checksum has not been requested, one byte should be deducted from the size of the object.
   That is: number of bytes = count × (size − 1).
5. The host reads the calculated number of message bytes. It is important that the host does *not* send a STOP condition during the message reads, as this will terminate the continuous read operation and reset the address pointer. No START and STOP conditions must be sent between the messages.
6. The host sends a STOP condition at the end of the read operation after the last message has been read. The NACK condition immediately before the STOP condition resets the address pointer to the start of the Message Count T44 object.

Figure 7-9 shows an example of using a continuous read operation to read three messages from the device without a checksum. Figure 7-10 shows the same example with a checksum.

FIGURE 7-9: CONTINUOUS MESSAGE READ EXAMPLE – NO CHECKSUM

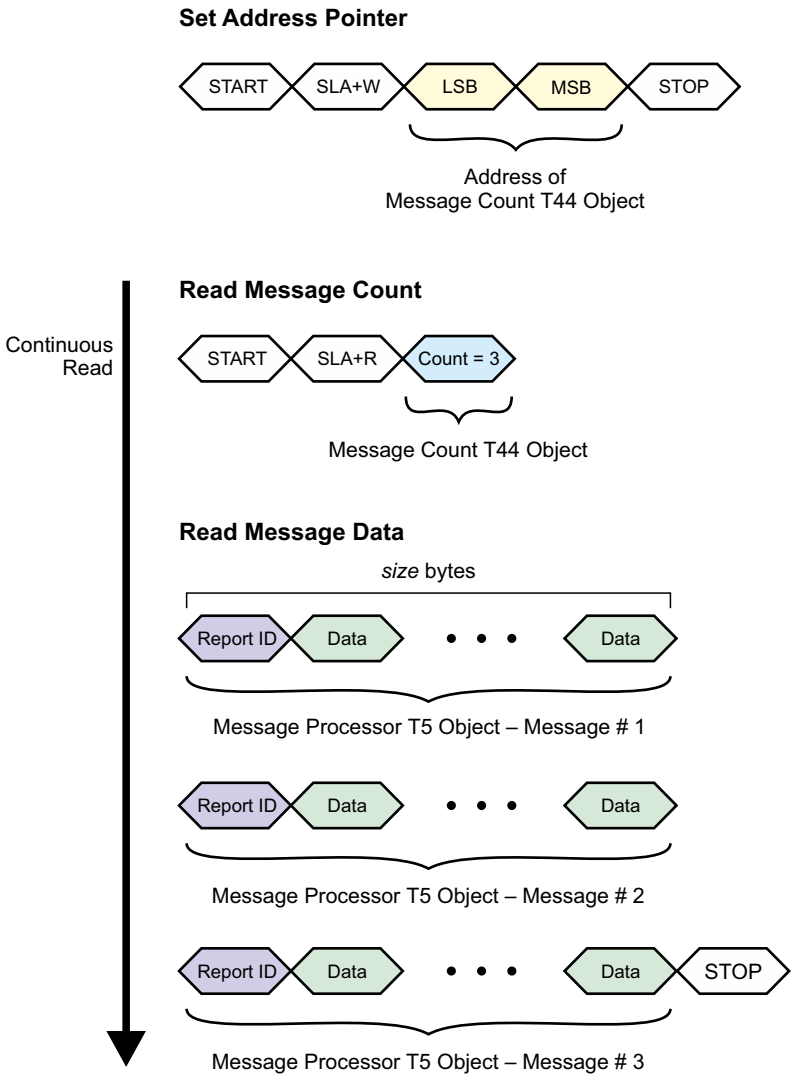
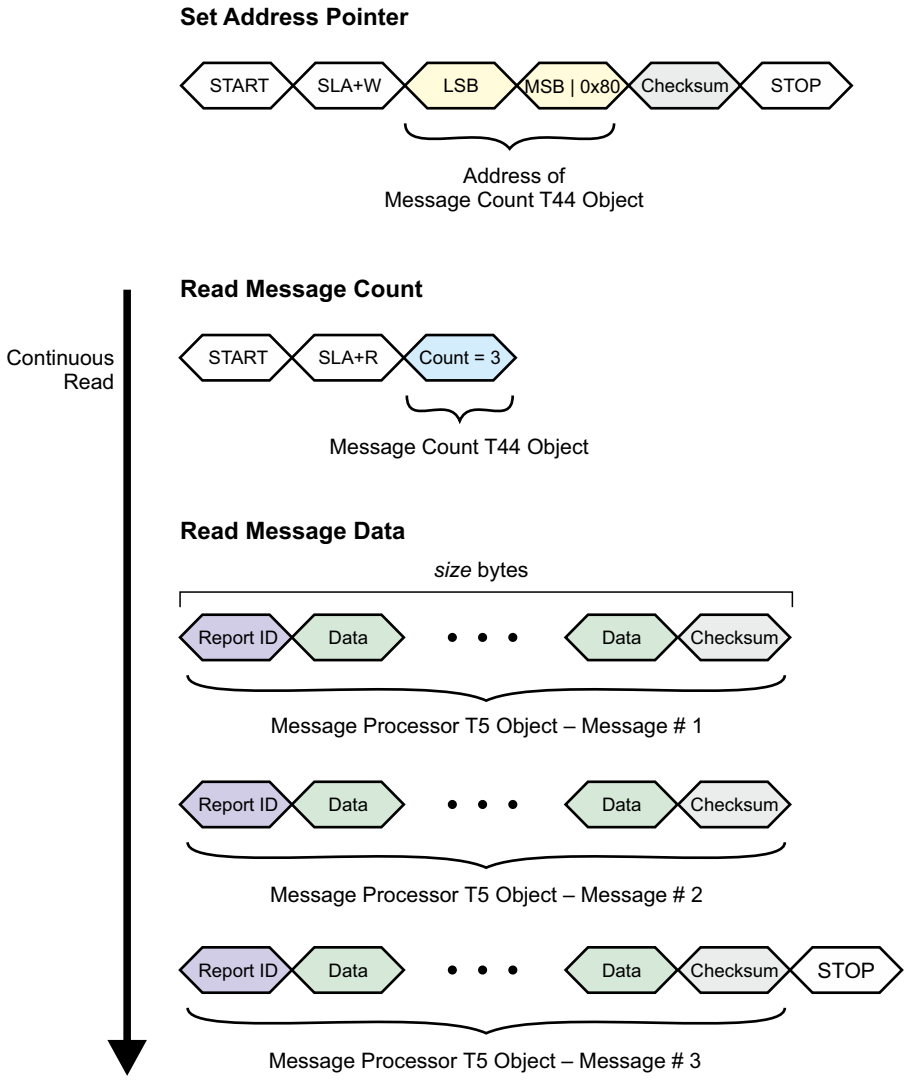
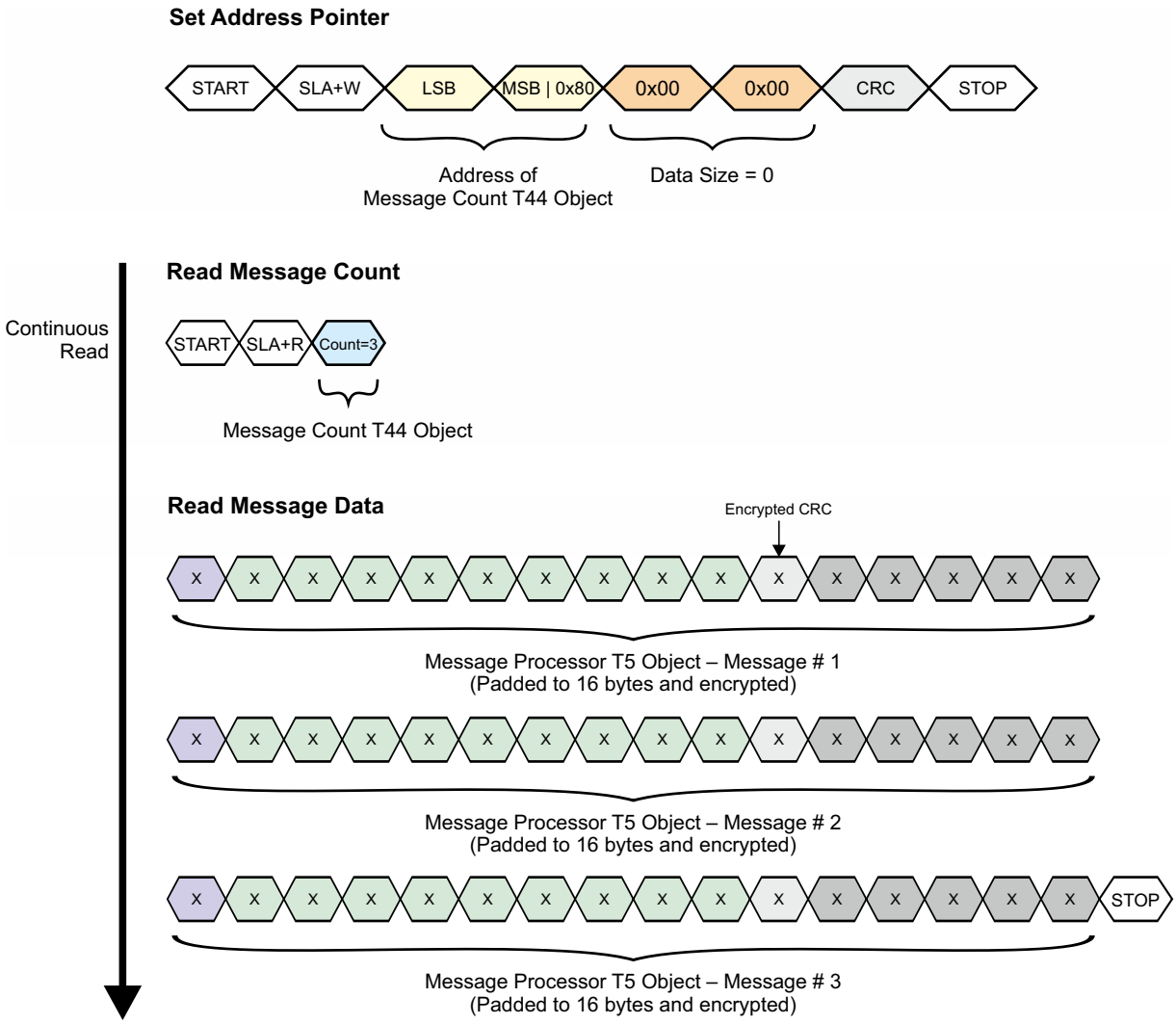


FIGURE 7-10: CONTINUOUS MESSAGE READ EXAMPLE – I²C CHECKSUM MODE



If encryption is enabled for Message Processor T5 message reads, then each message read using DMA will need to be decrypted. An example of this is shown in Figure 7-11. Note that this example also assumes the use of a CRC on the message reads, although this is not necessary.

FIGURE 7-11: EXAMPLE READ FROM MESSAGE PROCESSOR T5 – ENCRYPTION ACTIVE



NOTE: Example assumes CRC mode is being used.

7.5 $\overline{\text{CHG}}$ Line

The $\overline{\text{CHG}}$ line is an active-low, open-drain output that is used as an interrupt to alert the host that the client is ready to send a response or that an OBP message is pending and ready to be read from the host. This provides the host with an interrupt-style interface with the potential for fast response times. It reduces the need for wasteful I^2C communications.

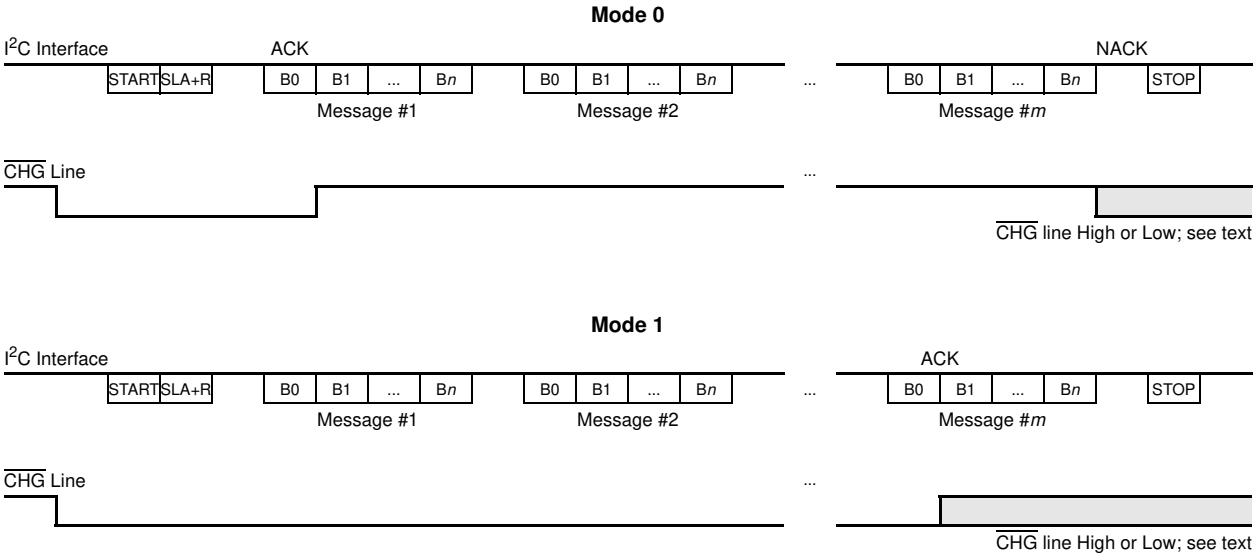
NOTE	The host should always use the $\overline{\text{CHG}}$ line as an indication that a message is ready to be read from the Message Processor T5 object; the host should never poll the device for messages.

The $\overline{\text{CHG}}$ line should always be configured as an input on the host during normal usage. This is particularly important after power-up or reset (see Section 5.0 “Power-up / Reset Requirements”).

A pull-up resistor is required to VddIO (see Section 2.0 “Schematic”).

The $\overline{CHG}$ line operates in two modes when it is used with I^2C communications, as defined by the Communications Configuration T18 object.

FIGURE 7-12: $\overline{CHG}$ LINE MODES FOR I^2C-COMPATIBLE TRANSFERS



In Mode 0 (edge-triggered operation):

1. The $\overline{CHG}$ line goes low to indicate that a message is present.
2. The $\overline{CHG}$ line goes high when the first byte of the first message (that is, its report ID) has been sent and acknowledged (ACK sent) and the next byte has been prepared in the buffer.
3. The STOP condition at the end of an I^2C transfer causes the $\overline{CHG}$ line to stay high if there are no more messages. Otherwise the $\overline{CHG}$ line goes low to indicate a further message.

Note that Mode 0 also allows the host to continually read messages by simply continuing to read bytes back without issuing a STOP condition. Message reading should end when a report ID of 255 (“invalid message”) is received. Alternatively the host ends the transfer by sending a NACK after receiving the last byte of a message, followed by a STOP condition. If there is another message present, the $\overline{CHG}$ line goes low again, as in step 1. In this mode the state of the $\overline{CHG}$ line does not need to be checked during the I^2C read.

In Mode 1 (level-triggered operation):

1. The $\overline{CHG}$ line goes low to indicate that a message is present.
2. The $\overline{CHG}$ line remains low while there are further messages to be sent after the current message.
3. The $\overline{CHG}$ line goes high again only once the first byte of the last message (that is, its report ID) has been sent and acknowledged (ACK sent) and the next byte has been prepared in the output buffer.

Mode 1 allows the host to continually read the messages until the $\overline{CHG}$ line goes high, and the state of the $\overline{CHG}$ line determines whether or not the host should continue receiving messages from the device.

NOTE	The state of the $\overline{CHG}$ line should be checked only between messages and not between the bytes of a message. The precise point at which the $\overline{CHG}$ line changes state cannot be predicted and so the state of the $\overline{CHG}$ line cannot be guaranteed between bytes.

The Communications Configuration T18 object can be used to configure the behavior of the $\overline{CHG}$ line. In addition to the $\overline{CHG}$ line operation modes described above, this object allows direct control over the state of the $\overline{CHG}$ line.

7.6 SDA and SCL

The I^2C bus transmits data and clock with SDA and SCL respectively. These are open-drain. The device can only drive these lines low or leave them open. The termination resistors (Rp) pull the line up to VddIO if no I^2C device is pulling it down.

The termination resistors should be chosen so that the rise times on SDA and SCL meet the I^2C specifications for the interface speed being used, bearing in mind other loads on the bus. For best latency performance, it is recommended that no other devices share the I^2C bus with the maXTouch controller.

7.7 Clock Stretching

The device supports clock stretching in accordance with the I^2C specification. It may also instigate a clock stretch if a communications event happens during a period when the device is busy internally. The maximum clock stretch is 2 ms and typically less than 350 µs.

8.0 PCB DESIGN CONSIDERATIONS

8.1 Introduction

The following sections give the design considerations that should be adhered to when designing a PCB layout for use with the mXT336UD-MAU002. Of these, power supply and ground tracking considerations are the most critical.

By observing the following design rules, and with careful preparation for the PCB layout exercise, designers will be assured of a far better chance of success and a correctly functioning product.

8.2 Printed Circuit Board

Microchip recommends the use of a four-layer printed circuit board for mXT336UD-MAU002 applications. This, together with careful layout, will ensure that the board meets relevant EMC requirements for both noise radiation and susceptibility, as laid down by the various national and international standards agencies.

8.2.1 PCB CLEANLINESS

Modern no-clean-flux is generally compatible with capacitive sensing circuits.

CAUTION!	If a PCB is reworked to correct soldering faults relating to any device, or to any associated traces or components, be sure that you fully understand the nature of the flux used during the rework process. Leakage currents from hygroscopic ionic residues can stop capacitive sensors from functioning. If you have any doubts, a thorough cleaning after rework may be the only safe option.

8.3 Power Supply

8.3.1 SUPPLY QUALITY

While the device has good Power Supply Rejection Ratio properties, poorly regulated and/or noisy power supplies can significantly reduce performance.

Particular care should be taken of the AVdd supply, as it supplies the sensitive analog stages in the device.

8.3.2 SUPPLY RAILS AND GROUND TRACKING

Power supply and clock distribution are the most critical parts of any board layout. Because of this, it is advisable that these be completed before any other tracking is undertaken. After these, supply decoupling, and analog and high speed digital signals should be addressed. Track widths for all signals, especially power rails should be kept as wide as possible in order to reduce inductance.

The Power and Ground planes themselves can form a useful capacitor. Flood filling for either or both of these supply rails, therefore, should be used where possible. It is important to ensure that there are no floating copper areas remaining on the board: all such areas should be connected to the ground plane. The flood filling should be done on the outside layers of the board.

8.3.3 POWER SUPPLY DECOUPLING

Decoupling capacitors should be fitted as specified in Section 2.2 “Schematic Notes”.

The decoupling capacitors must be placed as close as possible to the pin being decoupled. The traces from these capacitors to the respective device pins should be wide and take a straight route. They should be routed over a ground plane as much as possible. The capacitor ground pins should also be connected directly to a ground plane.

Surface mounting capacitors are preferred over wire-leaded types due to their lower ESR and ESL. It is often possible to fit these decoupling capacitors underneath and on the opposite side of the PCB to the digital ICs. This will provide the shortest tracking, and most effective decoupling possible.

8.3.4 VOLTAGE PUMP

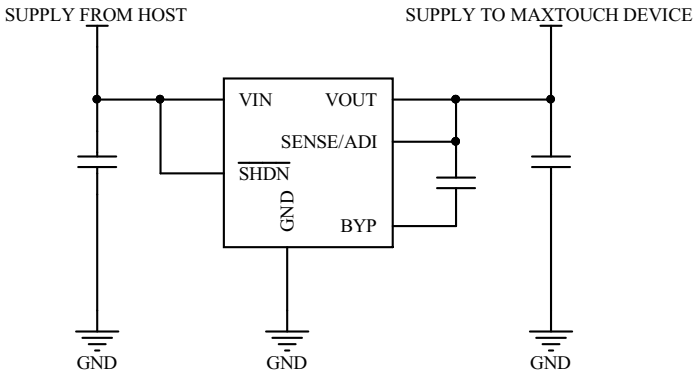
The traces for the voltage pump capacitor between EXTCAP0 and EXTCAP1 (Cd on the schematic in Section 2.0 “Schematic”) should be kept as short and as wide as possible for best pump performance. They should also be routed as parallel and as close as possible to each other in order to reduce emissions, and ideally the traces should be the same length.

8.3.5 VOLTAGE REGULATORS

Each supply rail requires a Low Drop-Out (LDO) voltage regulator, although an LDO can be shared where supply rails share the same voltage level.

Figure 8-1 shows an example circuit for an LDO.

FIGURE 8-1: EXAMPLE LDO CIRCUIT



An LDO regulator should be chosen that provides adequate output capability, low noise, no-load stability, good load regulation and step response. The mXT336UD-MAU002 has been qualified for use only with the Microchip LDOs listed in Table 8-1. However, some alternative LDOs with similar specifications are listed in Table 8-2. Microchip has not tested this maXTouch controller with any of these alternative LDOs. Microchip cannot guarantee the functionality or performance of this maXTouch controller with these or any other LDO besides those listed in Table 8-1.

NOTE Microchip recommends that a minimum of a 1.0 µF ceramic, low ESR capacitor at the input and output of these devices is always used. The datasheet for the device should always be referred to when selecting capacitors and the typical recommended values, types and dielectrics adhered to.

Sufficient output capacitance should be provided such that the output rate of rise is compatible with the mXT336UD-MAU002 power rail specifications (see Section 11.2.1 “DC Characteristics”). This can be achieved by a combination of output capacitance on the pins of the LDO and bulk capacitance at the inputs to the mXT336UD-MAU002.

TABLE 8-1: LDO REGULATORS – QUALIFIED FOR USE

Manufacturer	Device	Current Rating (mA)
Microchip Technology Inc.	MCP1824	300
Microchip Technology Inc.	MCP1824S	300
Microchip Technology Inc.	MAQ5300	300
Microchip Technology Inc.	MIC5504	300
Microchip Technology Inc.	MCP1725	500
Microchip Technology Inc.	MIC5514	300
Microchip Technology Inc.	MIC5323	300

TABLE 8-2: LDO REGULATORS – OTHER DEVICES

Manufacturer	Device	Current Rating (mA)
Analog Devices	ADP122/ADP123	300
Diodes Inc.	AP2125	300
Diodes Inc.	AP7335	300

TABLE 8-2: LDO REGULATORS – OTHER DEVICES (CONTINUED)

Manufacturer	Device	Current Rating (mA)
Linear Technology	LT1763CS8-3.3	500
NXP	LD6836	300
Texas Instruments	LP3981	300

8.3.6 SINGLE SUPPLY OPERATION

When designing a PCB for an application using a single LDO, extra care should be taken to ensure short, low inductance traces between the supply and the touch controller supply input pins. Ideally, tracking for the individual supplies should be arranged in a star configuration, with the LDO at the junction of the star. This will ensure that supply current variations or noise in one supply rail will have minimum effect on the other supplies. In applications where a ground plane is not practical, this same star layout should also apply to the power supply ground returns.

Only regulators with a 300 mA or greater rating can be used in a single-supply design.

Refer to the following application note for more information:

- Application Note: MXTAN0208 – *Design Guide for PCB Layouts for maXTouch Touch Controllers*

8.3.7 MULTIPLE VOLTAGE REGULATOR SUPPLY

The AVdd supply stability is critical for the device because this supply interacts directly with the analog front end. If noise problems exist when using a single LDO regulator, Microchip recommends that AVdd is supplied by a regulator that is separate from the digital supply. This reduces the amount of noise injected into the sensitive, low signal level parts of the design.

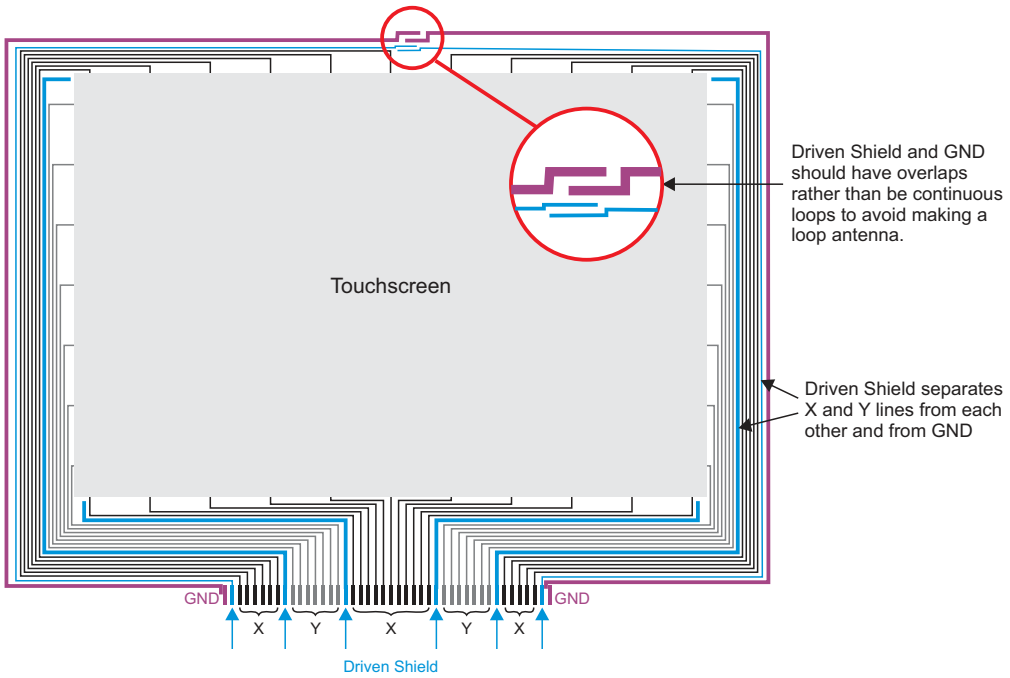
8.4 Driven Shield Line

The driven shield line is used to provide a guard track around the touchscreen panel that serves as Ground in mutual capacitance operation and as a driven shield in self capacitance operation.

The guard track must be routed between the groups of X tracks and the groups of Y tracks, as well as between the combined group of X/Y tracks and Ground. It should be fairly wide to avoid X-to-Y coupling in mutual capacitance operation, as the guard track will act as Ground in this circumstance.

A guard track is also needed between any self capacitance X/Y lines and mutual capacitance only X/Y lines (for example, between Multiple Touch Touchscreen T100 and Key Array T15 lines).

FIGURE 8-2: EXAMPLE DRIVEN SHIELD ROUTING



NOTE: Sample touchscreen for illustrative purposes only. The number of X/Y lines available on any given device might differ from that shown here. Similarly, the routing of the X/Y lines shown should not be taken as indicative of any preferred layout and the user's layout may vary.

8.5 ESD Ground Routing

To avoid damage due to ESD strikes, the outermost track on the sensor should be an ESD ground (see Figure 8-2). Like the driven shield, this should completely surround the sensor but with an overlap at the top rather than forming a complete loop.

To avoid electromagnetic induction of currents into the driven shield trace, a minimum separation of 0.3 mm should be maintained between the ESD GND trace and the Driven Shield.

The ESD ground traces should be connected to a dedicated ground trace in the PCB, and routed such that ESD strike currents do not flow under or close to the touch controller or the connecting wiring between it and the touchscreen array. The ESD ground should be connected in to the main system ground at a star point at the main GND connection to the PCB.

See also:

- MXTAN0208 – *Design guide for PCB Layouts for maXTouch Touch Controllers*

8.6 Analog I/O

In general, tracking for the analog I/O signals from the device should be kept as short as possible. These normally go to a connector which interfaces directly to the touchscreen.

Ensure that adequate ground-planes are used. An analog ground plane should be used in addition to a digital one. Care should be taken to ensure that both ground planes are kept separate and are connected together only at the point of entry for the power to the PCB. This is usually at the input connector.

8.7 Component Placement and Tracking

It is important to orient all devices so that the tracking for important signals (such as power and clocks) are kept as short as possible.

8.7.1 DIGITAL SIGNALS

In general, when tracking digital signals, it is advisable to avoid sharp directional changes on sensitive signal tracks (such as analog I/O) and any clock or crystal tracking.

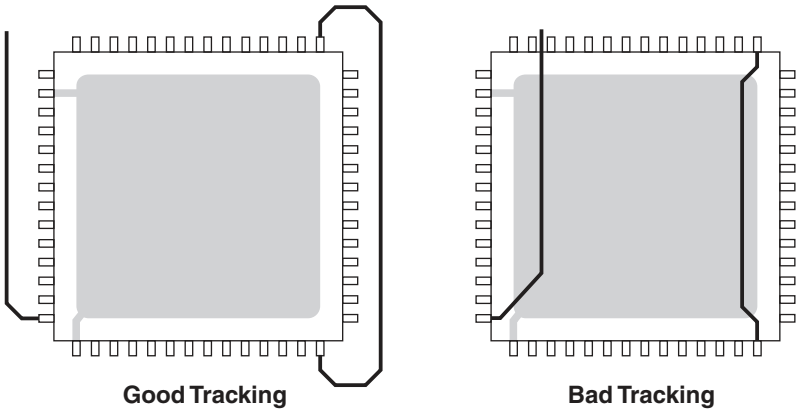
A good ground return path for all signals should be provided, where possible, to ensure that there are no discontinuities.

8.7.2 QFN PACKAGE RESTRICTIONS

The central pad on the underside of the QFN device should be connected to ground. Do not run any tracks underneath the body of the device on the top layer of the PCB, only ground. Figure 8-3 shows examples of good and bad tracking.

FIGURE 8-3: EXAMPLES OF GOOD AND BAD TRACKING

Note: The number of pins and their functions is shown for example purposes only and may not reflect the actual number or function on the device.



8.8 EMC and Other Observations

The following recommendations are not mandatory, but may help in situations where particularly difficult EMC or other problems are present:

- Try to keep as many signals as possible on the inside layers of the board. If suitable ground flood fills are used on the top and bottom layers, these will provide a good level of screening for noisy signals, both into and out of the PCB.
- Ensure that the on-board regulators have sufficient tracking around and underneath the devices to act as a heatsink. This heatsink will normally be connected to the 0 V or ground supply pin. Increasing the width of the copper tracking to any of the device pins will aid in removing heat. There should be no solder mask over the copper track underneath the body of the regulators.
- Ensure that the decoupling capacitors, especially high capacity ceramic type, have the requisite low ESR, ESL and good stability/temperature properties. Refer to the regulator manufacturer's datasheet for more information.

9.0 GETTING STARTED WITH MXT336UD-MAU002

9.1 Establishing Contact

9.1.1 COMMUNICATION WITH THE HOST

The host can use the following interface to communicate with the device:

- I^2C interface (see Section 7.0 “I2C Communications”)

9.1.2 POWER-UP SEQUENCE

The power-up sequence is as follows:

1. After the device has reset, the $\overline{CHG}$ line goes low to indicate to the host that a message is available. If the $\overline{CHG}$ line does not go low within a suitable timeout, there is a problem with the device. The timeout should be chosen to be, for example, three times the relevant typical values for the system as defined in Section 11.5.3 “Reset Timings” (for example, 1 second if all POST tests are performed).
2. Once the $\overline{CHG}$ line goes low, the host should attempt to read the first 7 bytes of memory from location 0x0000 (that is, the ID Information portion of the Information Block) to establish that the device is present and running following power-up. This should be done as part of the host’s initialization sequence (see Section 9.1.3 “Host Initialization”).
3. The device performs a checksum on the configuration settings held in the non-volatile memory. If the checksum does not match a stored copy of the last checksum, then this indicates that the settings have become corrupted. The host should write a correct configuration to the device, and issue a Command Processor T6 Backup command, if the read checksum does not match the expected checksum, or if the configuration error bit in the message data from the Command Processor T6 object is set.

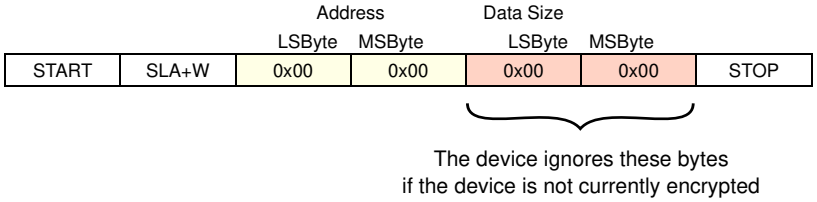
9.1.3 HOST INITIALIZATION

Once the device has powered up, the host should perform the following initialization steps so that it can communicate with the device:

1. Immediately after start-up (once the $\overline{CHG}$ line goes low), the host attempts to read the ID Information portion of the Information Block. The ID Information bytes are the first 7 bytes of memory, located at address 0x0000. This will be used to determine whether the device is encrypted or not, and therefore which communications protocol to use. A successful read will also confirm that the device is present and running following power-up.

   The write transfer to set the address pointer to 0x0000 must be sent using the encryption communications protocol, even if the device is currently unencrypted. If the device is expecting an encrypted format write transfer, it will expect, and accept, the entire write transfer. If, however, the device is not currently encrypted it will simply ignore the extra bytes in the write transfer (see Figure 9-1).

FIGURE 9-1: WRITE TRANSFER



2. Once the host has read the Information Block, the host should examine the Variant ID and use it to determine if encrypted communications are active. The Variant ID is the second byte in the Information Block (read in Step 1.).
   - If encryption is not active (default), the most significant bit will be set to 0 (that is, the Variant ID is 0x1C).
   - If encryption is active, the most significant bit will be set to 1 (that is, the Variant ID is 0x9C).
3. The host can now read the start positions of all the objects in the device from the Object Table and build up a list of the object addresses. Note that the number of Object Table elements was read by the host at start-up as part of the ID Information bytes. If encryption is active:
   a) Record the start position of the User Data T38 object (found in Step 3.).
   b) If encrypted configuration read/writes are enabled, use the address of the User Data T38 object to determine which objects will use encryption. These are the objects that are located after the User Data T38 object (that is, they have higher addresses).

4. Read the Encryption Status T2 object to determine which mode of encryption is enabled (that is, encrypted configuration read/writes and/or encrypted messages). This will determine the communications protocol to use to read or write configuration parameters and to read messages from the device. See Section 7.0 “I2C Communications” for more information.
5. Use the Object Table to calculate the report IDs so that messages from the device can be correctly interpreted.
6. Finally, read any pending messages generated during the start-up process. Note that Step 4. will have determined the communications protocol to use for reading messages.

9.2 Using the Object-based Protocol

The device has an object-based protocol (OBP) that is used to communicate with the device. Typical communication includes configuring the device, sending commands to the device, and receiving messages from the device.

9.2.1 CLASSES OF OBJECTS

The mXT336UD-MAU002 contains the following classes of objects:

- **Debug objects** – provide a raw data output method for development and testing.
- **General objects** – required for global configuration, transmitting messages and receiving commands.
- **Touch objects** – operate on measured signals from the touch sensor and report touch data.
- **Signal processing objects** – process data from other objects (typically signal filtering operations).
- **Support objects** – provide additional functionality on the device.

9.2.2 OBJECT INSTANCES

TABLE 9-1: OBJECTS ON THE MXT336UD-MAU002

Object	Description	Number of Instances	Usage
Debug Objects			
Diagnostic Debug T37	Allows access to diagnostic debug data to aid development.	1	Debug commands only; Read-only object. No configuration or tuning necessary. Not for use in production. Debug data is not encrypted.
General Objects			
Encryption Status T2	Provides information on the configuration encryption status.	1	Read-only object; no configuration necessary. Object is not encrypted.
Message Processor T5	Handles the transmission of messages. This object holds a message in its memory space for the host to read.	1	Read-only object; no configuration necessary. Messages can be encrypted.
Command Processor T6	Performs a command when written to. Commands include reset, calibrate and backup settings.	1	No configuration necessary. Object is not encrypted.
Power Configuration T7	Controls the sleep mode of the device. Power consumption can be lowered by controlling the acquisition frequency and the sleep time between acquisitions.	1	Must be configured before use. Configuration read/writes may be encrypted.
Acquisition Configuration T8	Controls how the device takes each capacitive measurement.	1	Must be configured before use. Configuration read/writes may be encrypted.
Touch Objects			
Key Array T15	Defines a rectangular array of keys. A Key Array T15 object reports simple on/off touch information.	1	Enable and configure as required. Configuration read/writes may be encrypted.
Multiple Touch Touchscreen T100	Creates a touchscreen that supports the tracking of more than one touch.	1	Enable and configure as required. Configuration read/writes may be encrypted.

TABLE 9-1: OBJECTS ON THE MXT336UD-MAU002 (CONTINUED)

Object	Description	Number of Instances	Usage
Signal Processing Objects			
Grip Suppression T40	Suppresses false detections caused, for example, by the user gripping the edge of a touchscreen.	1	Enable and configure as required. Configuration read/writes may be encrypted.
Touch Suppression T42	Suppresses false detections caused by unintentional large touches by the user.	1	Enable and configure as required. Configuration read/writes may be encrypted.
Passive Stylus T47	Processes passive stylus input.	1	Enable and configure as required. Configuration read/writes may be encrypted.
Shieldless T56	Allows a sensor to use true single-layer co-planar construction.	1	Enable and configure as required. Configuration read/writes may be encrypted.
Lens Bending T65	Compensates for lens deformation (lens bending) by attempting to eliminate the disturbance signal from the reported deltas.	3	Enable and configure as required. Configuration read/writes may be encrypted.
Noise Suppression T72	Performs various noise reduction techniques during sensor signal acquisition.	1	Enable and configure as required. Configuration read/writes may be encrypted.
Glove Detection T78	Allows for the reporting of glove touches.	1	Enable and configure as required. Configuration read/writes may be encrypted.
Retransmission Compensation T80	Limits the negative effects on touch signals caused by poor device coupling to ground or moisture on the sensor.	1	Enable and configure as required. Configuration read/writes may be encrypted.
Self Capacitance Noise Suppression T108	Suppresses the effects of external noise within the context of self capacitance touch measurements.	1	Enable and configure as required. Configuration read/writes may be encrypted.
Support Objects			
Self Test Control T10	Controls the self-test routines to find faults on the touch sensor.	1	Enable and configure as required. Configuration read/writes may be encrypted.
Self Test Pin Faults T11	Specifies the configuration settings for the Pin Fault self tests.	1	Configure as required. Configuration read/writes may be encrypted.
Self Test Signal Limits T12	Specifies the configuration settings for the Signal Limit self tests.	2	Configure as required. Configuration read/writes may be encrypted.
Communications Configuration T18	Configures additional communications behavior for the device.	1	Check and configure as necessary. Configuration read/writes may be encrypted.
GPIO Configuration T19	Allows the host controller to configure and use the general purpose I/O pins on the device.	1	Enable and configure as required. Configuration read/writes may be encrypted.
User Data T38	Provides a data storage area for user data.	1	Configure as required. Object is not encrypted.
Message Count T44	Provides a count of pending messages.	1	Read-only object; no configuration necessary. Object is not encrypted.
CTE Configuration T46	Controls the capacitive touch engine for the device.	1	Must be configured. Configuration read/writes may be encrypted.
Timer T61	Provides control of a timer.	6	Enable and configure as required. Configuration read/writes may be encrypted.

TABLE 9-1: OBJECTS ON THE MXT336UD-MAU002 (CONTINUED)

Object	Description	Number of Instances	Usage
Serial Data Command T68	Provides an interface for the host driver to deliver various data sets to the device.	1	Enable and configure as required. Object is not encrypted.
Dynamic Configuration Controller T70	Allows rules to be defined that respond to system events.	20	Enable and configure as required. Configuration read/writes may be encrypted.
Dynamic Configuration Container T71	Allows the storage of user configuration on the device that can be selected at runtime based on rules defined in the Dynamic Configuration Controller T70 object.	1	Configure if Dynamic Configuration Controller T70 is in use. Configuration read/writes may be encrypted.
Auxiliary Touch Configuration T104	Allows the setting of self capacitance gain and thresholds for a particular measurement to generate auxiliary touch data for use by other objects.	1	Enable and configure if using self capacitance measurements. Configuration read/writes may be encrypted.
Self Capacitance Global Configuration T109	Provides configuration for self capacitance measurements employed on the device.	1	Check and configure as required (if using self capacitance measurements). Configuration read/writes may be encrypted.
Self Capacitance Tuning Parameters T110	Provides configuration space for a generic set of settings for self capacitance measurements.	4	Use under the guidance of Microchip field engineers only. Configuration read/writes may be encrypted.
Self Capacitance Configuration T111	Provides configuration for self capacitance measurements employed on the device.	2	Check and configure as required (if using self capacitance measurements). Configuration read/writes may be encrypted.
Self Capacitance Measurement Configuration T113	Configures self capacitance measurements to generate data for use by other objects.	1	Enable and configure as required. Configuration read/writes may be encrypted.

9.2.3 CONFIGURING AND TUNING THE DEVICE

The objects are designed such that a default value of zero in their fields is a “safe” value that typically disables functionality. The objects must be configured before use and the settings written to the non-volatile memory using the Command Processor T6 object.

Perform the following actions for each object:

1. Enable the object, if the object requires it.
2. Configure the fields in the object, as required.
3. Enable reporting, if the object supports messages, to receive messages from the object.

9.3 Writing to the Device

The following mechanism can be used to write to the device:

- Using an I^2C write operation (see Section 7.2 “Writing To the Device”).

Communication with the device is achieved by writing to the appropriate object:

- To send a command to the device, an appropriate command is written to the Command Processor T6 object.
- To configure the device, a configuration parameter is written to the appropriate object. For example, writing to the Power Configuration T7 configures the power consumption for the device and writing to the Multiple Touch Touchscreen T100 object sets up the touchscreen. Some objects are optional and need to be enabled before use.

IMPORTANT!	When the host issues any command within an object that results in a flash write to the device Non-Volatile Memory (NVM), that object should have its CTRL RPTEN bit set to 1, if it has one. This ensures that a message from the object writing to the NVM is generated at the completion of the process and an assertion of the $\overline{\text{CHG}}$ line is executed. The host must also ensure that the assertion of the $\overline{\text{CHG}}$ line refers to the expected object report ID before asserting the $\overline{\text{RESET}}$ line to perform a reset. Failure to follow this guidance may result in a corruption of device configuration area and the generation of a CFGERR.

9.3.1 WRITING A CONFIGURATION TO THE DEVICE

During a configuration download, device operation may be based upon only part of that configuration because it is yet to finish downloading. In rare circumstances, the total processing time might exceed the WDT reset time. This is more likely to happen when measurements take a long time to perform due to the partial configuration.

To ensure that the configuration is written safely, follow these steps:

1. Set Power Configuration T7 IDLEACQINT and ACTVACQINT to 0 (that is, deep sleep) as a temporary measure.
2. Download the rest of the configuration, except those Power Configuration T7 controls.
3. Finally, set the Power Configuration T7 acquisition interval controls to the required values.

9.4 Reading from the Device

Status information is stored in the Message Processor T5 object. This object can be read to receive any status information from the device.

The $\overline{\text{CHG}}$ line is asserted whenever a new message is available in the Message Processor T5 object (see Section 7.5 “CHG Line”). See Section 7.4 “Reading From the Device” for information on the format of the I^2C read operation.

NOTE	The host should always wait to be notified of messages; the host should not poll the device for messages, either by polling the Message Processor T5 object or by polling the $\overline{\text{CHG}}$ line.

10.0 DEBUGGING AND TUNING

10.1 SPI Debug Interface

The SPI Debug Interface is used for tuning and debugging when running the system and allows the development engineer to use Microchip maXTouch Studio to read the real-time raw data. This uses the low-level debug port.

The SPI Debug Interface consists of the $\overline{\text{DBG\_SS}}$, DBG_CLK and DBG_DATA lines. These lines should be routed to test points on all designs such that they can be connected to external hardware during system development. These lines should not be connected to power or GND. See Section 2.2.11 “SPI Debug Interface” for more details.

The SPI Debug Interface is enabled by the Command Processor T6 object and by default will be off.

NOTE	When the $\overline{\text{DBG\_SS}}$, DBG_CLK and DBG_DATA lines are in use for debugging, any alternative function for the pins cannot be used. The touch controller will take care of the pin configuration.

10.2 Object-based Protocol

The device provides a mechanism for obtaining debug data for development and testing purposes by reading data from the Diagnostic Debug T37 object.

NOTE	The Diagnostic Debug T37 object is of most use for simple tuning purposes. When debugging a design, it is preferable to use the SPI Debug Interface, as this will have a much higher bandwidth and can provide real-time data.

10.3 Self Test

The Self Test Control T10, Self Test Pin Faults T11 and Self Test Signal Limits T12 objects run self-test routines in the device to find hardware faults in the device both at power-on/reset and during normal operation. These self-test routines can be configured to check the power supplies of the devices, as well as the signal levels. The tests can also check for pin shorts between sensor X and Y pins, and between the sensor lines and DS0, power or GND pins.

The Self Test Control T10 object can also provide continuous monitoring of the health of the device while it is in operation. A periodic Built-In Self Test (BIST) test can be run at a user-specified interval and reports the global pass and specific fail messages (as determined by the device configuration). Reporting is achieved either by standard Self Test Control T10 object protocol messages or by a configurable hardware GPIO pin, configured using the GPIO Configuration T19 object.

For a list of the self tests available on the mXT336UD-MAU002, see Table 10-1.

TABLE 10-1: SELF TESTS

	Run as…			
Self Test Group	**Pre-Operation Self Test (POST)**	**Built-In Self Test (BIST)**	**On Demand Test**	
Power	Yes	Yes	Yes	} Internal System
Pin Faults	Yes	Yes	Yes	} CTE and Touch System
Signal Limits	Yes	Yes	Yes	} CTE and Touch System

11.0 SPECIFICATIONS

11.1 Absolute Maximum Specifications

Vdd	3.6V
VddIO	3.6V
AVdd	3.6V
Maximum continuous combined pin current, all GPIO*n* pins	40 mA
Voltage forced onto any pin	–0.3 V to (Vdd, VddIO or AVdd) + 0.3 V
Configuration parameters maximum writes	10,000
Maximum junction temperature	125°C

CAUTION! Stresses beyond those listed under *Absolute Maximum Specifications* may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum specification conditions for extended periods may affect device reliability.

11.2 Recommended Operating Conditions

Operating temperature	–40°C to +85°C
Storage temperature	–60°C to +150°C
Vdd	3.3 V
VddIO	1.8 V to 3.3 V
AVdd	3.3 V
XVdd with internal voltage doubler	2 × AVdd
XVdd low voltage operation (without internal voltage doubler)	Connected to AVdd
Temperature slew rate	10°C/min

11.2.1 DC CHARACTERISTICS

11.2.1.1 Analog Voltage Supply – AVdd

Parameter	Min	Typ	Max	Units	Notes
AVdd					
Operating limits	3.0	3.3	3.47	V	
Supply Rise Rate	–	–	0.036	V/µs	For example, for a 3.3 V rail, the voltage should take a minimum of 92 µs to rise

11.2.1.2 Digital Voltage Supply – VddIO, Vdd

Parameter	Min	Typ	Max	Units	Notes
VddIO					
Operating limits – Normal Voltage	2.7	3.3	3.47	V	
Operating limits – Low Voltage	1.71	1.8	1.89	V	
Supply Rise Rate	–	–	0.036	V/µs	For example, for a 3.3 V rail, the voltage should take a minimum of 92 µs to rise
Vdd					
Operating limits	2.7	3.3	3.47	V	
Supply Rise Rate	–	–	0.036	V/µs	For example, for a 3.3 V rail, the voltage should take a minimum of 92 µs to rise
Supply Fall Rate	–	–	0.05	V/µs	For example, for a 3.3 V rail, the voltage should take a minimum of 66 µs to fall

11.2.1.3 XVdd Voltage Supply – XVdd

Parameter	Min	Typ	Max	Units	Notes
XVdd					
Operating limits – voltage doubler enabled	–	2 × AVdd	–	V	
Operating limits – voltage doubler disabled	–	AVdd	–	V	

11.2.2 POWER SUPPLY RIPPLE AND NOISE

Parameter	Min	Typ	Max	Units	Notes
Vdd	–	–	±50	mV	Across frequency range 1 Hz to 1 MHz
AVdd	–	–	±40	mV	Across frequency range 1 Hz to 1 MHz, with Noise Suppression enabled

11.3 Test Configuration

The configuration values listed below were used in the reference unit to validate the interfaces and derive the characterization data provided in the following sections.

TABLE 11-1: TEST CONFIGURATION

Object/Parameter or Feature	Description/Setting (Numbers in Decimal)
Power Configuration T7	
CFG2	0 (Power Monitor Enabled)
Acquisition Configuration T8	
CHRGTIME	40
MEASALLOW	11
Self Test Control T10	Object Enabled; Reporting Enabled; BIST Reporting Enabled; POST Reporting Enabled
POSTCFG	All Power, Signal Limits and Pin Fault tests enabled
BISTCFG	All Power, Signal Limits and Pin Fault tests enabled
GPIO Configuration T19	Object Enabled
Touch Suppression T42	Object Enabled
CTE Configuration T46	
IDLESYNCSPERX	8
ACTVSYNCSPERX	8
Passive Stylus T47	Object Enabled
Shieldless T56	
INTTIME	22
Lens Bending T65 Instance 0	Object Instance Enabled
Noise Suppression T72	Object Enabled
Glove Detection T78	Object Enabled
Retransmission Compensation T80	Object Enabled
Multiple Touch Touchscreen T100	Object Enabled; Reporting Enabled
XSIZE	14
YSIZE	24
Auxiliary Touch Configuration T104	Object Enabled
Self Capacitance Noise Suppression T108	Object Enabled
Self Capacitance Configuration T111 Instance 0	
INTTIME	50
IDLESYNCSPERL	24
ACTVSYNCSPERL	24
Self Capacitance Configuration T111 Instance 1	
INTTIME	50
IDLESYNCSPERL	32
ACTVSYNCSPERL	32
Self Capacitance Measurement Configuration T113	Object Enabled
Device Encryption	Not active

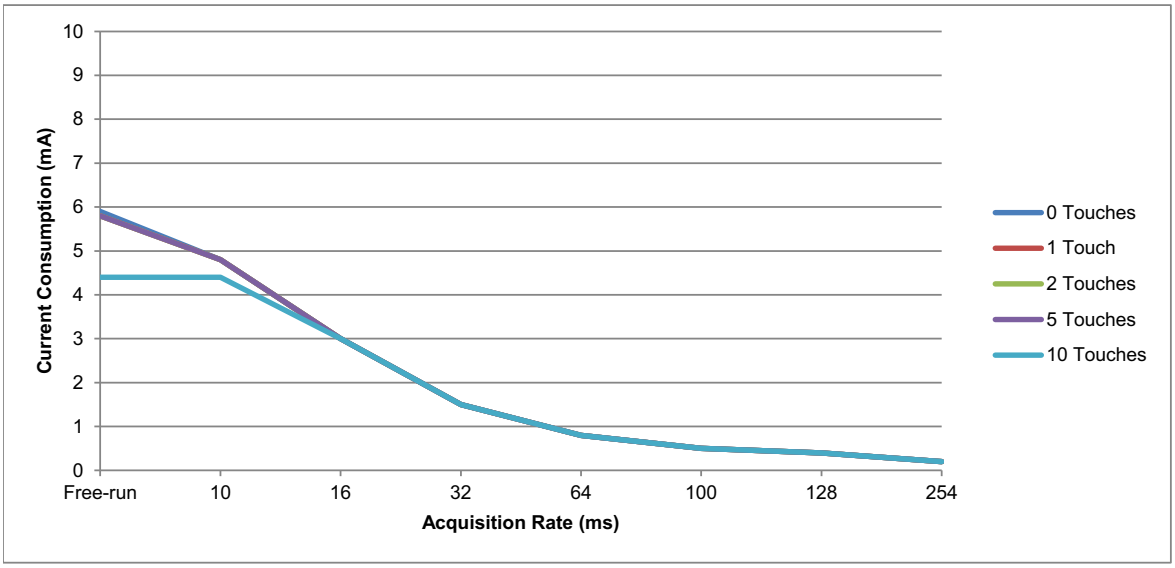
11.4 Current Consumption – I²C Interface

NOTE The characterization charts show typical values based on the configuration in Table 11-1. Actual power consumption in the user's application will depend on the circumstances of that particular project and will vary from that shown here. Further tuning will be required to achieve an optimal performance.

Note also that the use of encryption has no noticeable effect on power consumption.

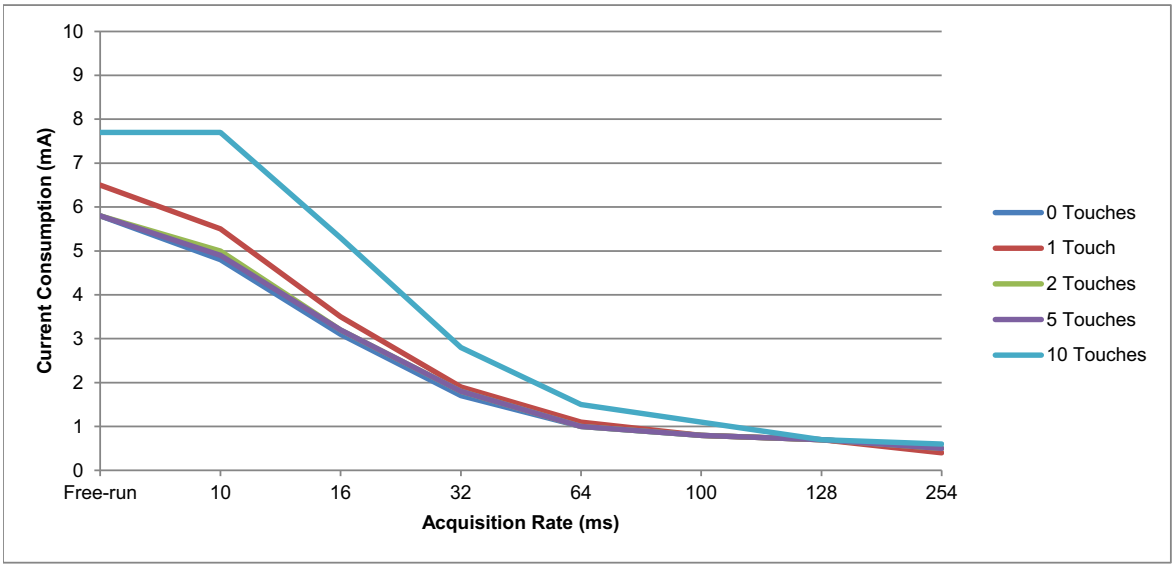
11.4.1 AVDD 3.3V

	Current Consumption (mA)				
Acquisition Rate (ms)	**0 Touches**	**1 Touch**	**2 Touches**	**5 Touches**	**10 Touches**
Free-run	5.9	5.8	5.8	5.8	4.4
10	4.8	4.8	4.8	4.8	4.4
16	3	3	3	3	3
32	1.5	1.5	1.5	1.5	1.5
64	0.8	0.8	0.8	0.8	0.8
100	0.5	0.5	0.5	0.5	0.5
128	0.4	0.4	0.4	0.4	0.4
254	0.2	0.2	0.2	0.2	0.2



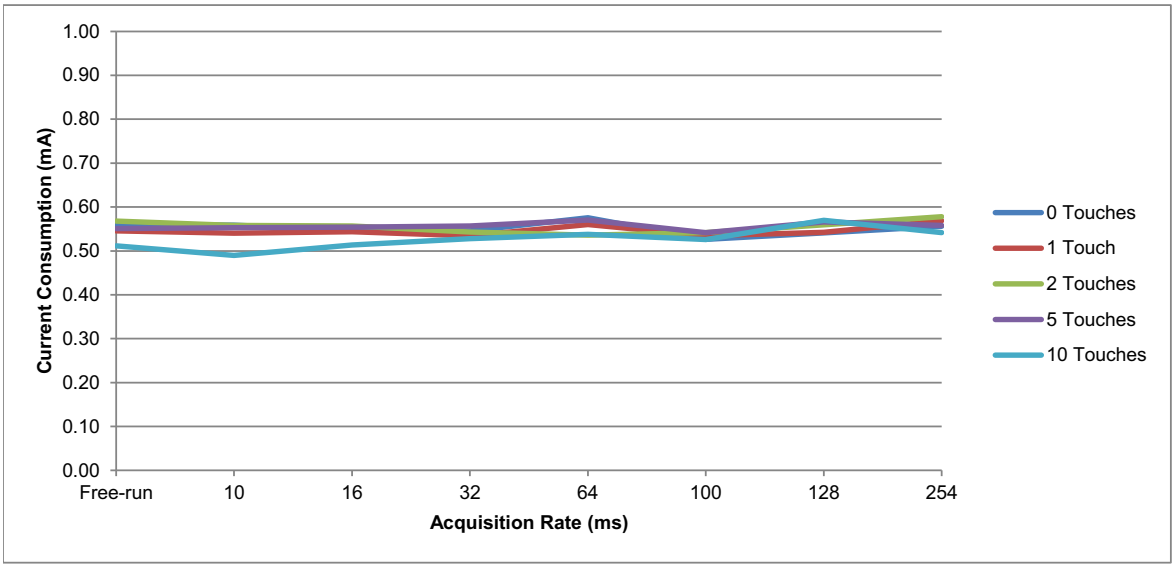
11.4.2 VDD 3.3V

	Current Consumption (mA)				
Acquisition Rate (ms)	**0 Touches**	**1 Touch**	**2 Touches**	**5 Touches**	**10 Touches**
Free-run	5.8	6.5	5.8	5.8	7.7
10	4.8	5.5	5	4.9	7.7
16	3.1	3.5	3.2	3.2	5.3
32	1.7	1.9	1.8	1.8	2.8
64	1	1.1	1	1	1.5
100	0.8	0.8	0.8	0.8	1.1
128	0.7	0.7	0.7	0.7	0.7
254	0.5	0.4	0.5	0.5	0.6



11.4.3 VDDIO 1.8V

	Current Consumption (mA)				
Acquisition Rate (ms)	**0 Touches**	**1 Touch**	**2 Touches**	**5 Touches**	**10 Touches**
Free-run	0.56	0.55	0.57	0.55	0.51
10	0.56	0.54	0.56	0.55	0.49
16	0.55	0.54	0.56	0.55	0.51
32	0.55	0.53	0.54	0.56	0.53
64	0.58	0.56	0.54	0.57	0.54
100	0.53	0.53	0.54	0.54	0.53
128	0.54	0.54	0.56	0.57	0.57
254	0.56	0.57	0.58	0.56	0.54



11.4.4 DEEP SLEEP

T_A = 25°C

Parameter	**Power Monitoring On**		**Power Monitoring Off**	**Units**	**Notes**
	Sampling Mode	**Continuous Mode**			
Deep Sleep Current	0.73	1.52	0.59	mA	Vdd = 3.3V, AVdd = 3.3V, VddIO = 1.8V
Deep Sleep Power	1.61	3.97	1.14	mW	

11.5 Timing Specifications

NOTE The figures below show typical values based on the test configuration. Actual timings in the user's application will depend on the circumstances of that particular project and will vary from those shown below. Further tuning will be required to achieve an optimal performance.

11.5.1 TOUCH LATENCY

Conditions: XSIZE = 14; YSIZE = 24; CHRGTIME = 40; IDLESYNCSPERX = 8; ACTVSYNCSPERX = 8;
T = ambient temperature; Finger center of screen; Reporting off (except T100)

Idle Primary = Mutual Capacitance; Active Primary = Mutual Capacitance

	Pipelining Off			Pipelining On			
T100 TCHDIDOWN	Min	Typ	Max	Min	Typ	Max	Units
3	28.6	32.1	36.8	31.1	35.4	38.9	ms
2	20.7	24.9	39.4	22.1	26.8	30.7	ms
1	12.7	16.5	20.2	12.4	16.2	20.4	ms

Idle Primary = Self Capacitance; Active Primary = Mutual Capacitance

	Pipelining Off			Pipelining On			
T100 TCHDIDOWN	Min	Typ	Max	Min	Typ	Max	Units
3	28.7	31.8	34.9	30.6	33.4	36.9	ms
2	20.4	23.3	26.4	22.7	25.8	28.9	ms
1	12.3	15	17.7	12.6	15.4	23.3	ms

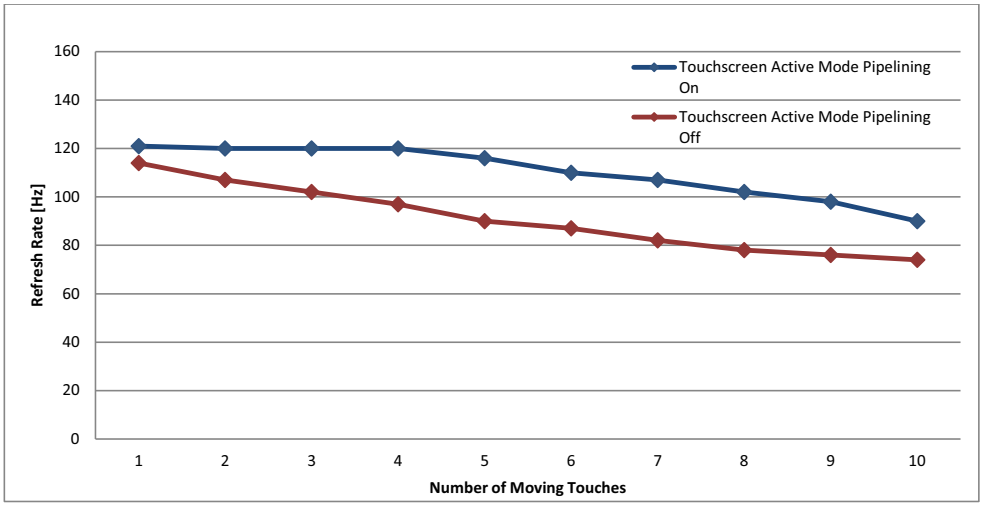
Idle Primary = Self Capacitance; Active Primary = Self Capacitance

	Pipelining Off			Pipelining On			
T100 TCHDIDOWN	Min	Typ	Max	Min	Typ	Max	Units
3	26.6	28.2	30.5	27.8	30.5	32.7	ms
2	18.7	21.5	24.4	20.6	23.3	26.6	ms
1	12.3	15.1	18.1	12	15.1	18.2	ms

11.5.2 REPORT RATE

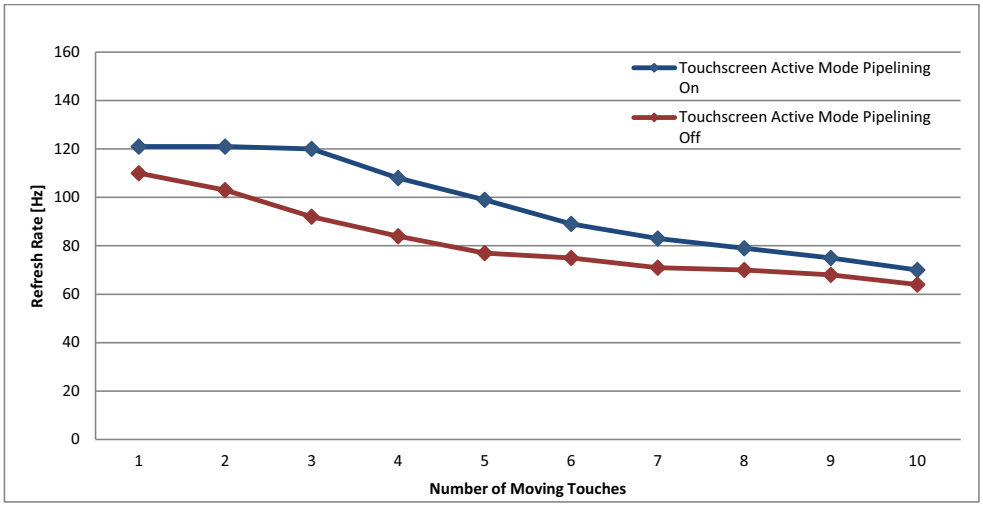
11.5.2.1 Encryption Not Active

Conditions: XSIZE = 14; YSIZE = 24; CHRGTIME = 40; IDLESYNCSPERX = 8; ACTVSYNCSPERX = 8; T = ambient temperature



11.5.2.2 Encryption Active

Conditions: XSIZE = 14; YSIZE = 24; CHRGTIME = 40; IDLESYNCSPERX = 8; ACTVSYNCSPERX = 8; T = ambient temperature



11.5.3 RESET TIMINGS

Parameter	Power-on Features (Typ) [2]		Units	Notes
	Disabled	Enabled		
Power on to $\overline{\text{CHG}}$ line low	48	70	ms	Triggered by Vdd supply at start up
Hardware reset to $\overline{\text{CHG}}$ line low	47	70	ms	Triggered by $\overline{\text{RESET}}$
Software reset to $\overline{\text{CHG}}$ line low	69	90	ms	Triggered by Command Processor T6 Reset command

Note 1: Any $\overline{\text{CHG}}$ line activity before the power-on or reset period has expired should be ignored by the host. Operation of this signal cannot be guaranteed before the power-on/reset periods have expired.

2: Power-on features include POST self tests and device encryption. Figures show typical values for extreme cases; that is, with all features disabled and with all features enabled.

11.6 Touch Accuracy and Repeatability

Parameter	Min	Typ	Max	Units	Notes
Linearity	–	±0.5	–	mm	Finger diameter 8 mm
Accuracy (across all areas of screen)	–	0.5	–	mm	Finger diameter 8 mm
Repeatability	–	±0.25	–	%	X axis with 12-bit resolution

11.7 Touchscreen Sensor Characteristics

Parameter	Description	Value
Cm	Mutual capacitance	Typical value is between 0.15 pF and 10 pF on a single node.
Cpx	Mutual capacitance load to X	Microchip recommends a maximum load of 300 pF on each X or Y line. [1]
	With Internal Voltage Pump	Maximum recommended load on each X line: [2] Cpx + (*num_Y* × Cm) < 240 pF
	With Internal Voltage Pump and Dual X	Maximum recommended load on each X line: [2] Cpx + (2 × *num_Y* × Cm) < 120 pF
Cpy	Mutual capacitance load to Y	Microchip recommends a maximum load of 300 pF on each X or Y line. [1]
Cpx	Self capacitance load to X	Microchip recommends a maximum load of 130 pF on each X or Y line. [1]
Cpy	Self capacitance load to Y	
ΔCpx	Self capacitance imbalance on X	Nominal value is 14.8 pF. Value increases by 1 pF for every 45 pF reduction in Cpx/Cpy (based on 100 pF load)
ΔCpy	Self capacitance imbalance on Y	
Cpds0	Self capacitance load to Driven Shield	Microchip recommends a maximum load of 130 pF on the Driven Shield line. [1]

Note 1: Please contact your Microchip representative for advice if you intend to use higher values.

2: *num_Y* = Number of active Y lines defined by Multiple Touch Touchscreen T100.

11.8 Input/Output Characteristics

Parameter	Description	Min	Typ	Max	Units	Notes
Input (All input pins connected to the VddIO power rail)						
Vil	Low input logic level	–0.3	–	0.3 × VddIO	V	VddIO = 1.8 V to Vdd
Vih	High input logic level	0.7 × VddIO	–	VddIO	V	VddIO = 1.8 V to Vdd
Iil	Input leakage current	–	–	1	µA	

Parameter	Description	Min	Typ	Max	Units	Notes
$\overline{\text{RESET}}$ /GPIO	Internal pull-up resistor	9	10	16	kΩ	
Input (All input pins connected to the Vdd power rail)						
Vil	Low input logic level	–0.3	–	0.3 × Vdd	V	
Vih	High input logic level	0.7 × Vdd	–	Vdd	V	
Iil	Input leakage current	–	–	1	µA	Pull-up resistors disabled
GPIOs	Internal pull-up/pull-down resistor	9	10	16	kΩ	
Output (All output pins connected to the VddIO power rail)						
Vol	Low output voltage	0	–	0.2 × VddIO	V	VddIO = 1.8 V to Vdd Iol = max 0.4 mA
Voh	High output voltage	0.8 × VddIO	–	VddIO	V	VddIO = 1.8 V to Vdd Ioh = 0.4 mA
Output (All output pins connected to the Vdd power rail)						
Vol	Low output voltage	0	–	0.2 × Vdd	V	Iol = max 0.4 mA
Voh	High output voltage	0.8 × Vdd	–	Vdd	V	Ioh = 0.4 mA

11.9 I²C Specification

Parameter	Value
Address	0x4A
I²C specification (1)	Revision 6.0
Maximum bus speed (SCL) (2)	1 MHz
Standard Mode (3)	100 kHz
Fast Mode (3)	400 kHz
Fast Mode Plus (3)	1 MHz

Note 1: More detailed information on I²C operation is available from UM10204, *I²C bus specification and user manual*, available from NXP.

2: In systems with heavily laden I²C lines, even with minimum pull-up resistor values, bus speed may be limited by capacitive loading to less than the theoretical maximum.

3: The values of pull-up resistors should be chosen to ensure SCL and SDA rise and fall times meet the I²C specification. The value required will depend on the amount of capacitance loading on the lines.

11.10 Thermal Packaging

11.10.1 THERMAL DATA

Parameter	Description	Typ	Unit	Condition	Package
θ_{JA}	Junction to ambient thermal resistance	33.7	°C/W	Still air	56-pin XQFN 6 × 6 × 0.4 mm
θ_{JC}	Junction to case thermal resistance	10.1	°C/W		56-pin XQFN 6 × 6 × 0.4 mm

11.10.2 JUNCTION TEMPERATURE

The maximum junction temperature allowed on this device is 125°C.

The average junction temperature in °C (T_J) for this device can be obtained from the following:

$$T_J = T_A + (P_D \times \theta_{JA})$$

If a cooling device is required, use this equation:

$$T_J = T_A + (P_D \times (\theta_{HEATSINK} + \theta_{JC}))$$

where:

- θ_{JA}= package thermal resistance, Junction to ambient (°C/W) (see Section 11.10.1 “Thermal Data”)
- θ_{JC} = package thermal resistance, Junction to case thermal resistance (°C/W) (see Section 11.10.1 “Thermal Data”)
- $\theta_{HEATSINK}$ = cooling device thermal resistance (°C/W), provided in the cooling device datasheet
- P_D = device power consumption (W)
- T_A is the ambient temperature (°C)

11.11 ESD Information

Parameter	Value	Reference Standard
Human Body Model (HBM)	±2000V	JEDEC JS–001
Charge Device Model (CDM)	±250V	JEDEC JS–001

11.12 Soldering Profile

Profile Feature	Green Package
Average Ramp-up Rate (217°C to Peak)	3°C/s max
Preheat Temperature 175°C ±25°C	150 – 200°C
Time Maintained Above 217°C	60 – 150 s
Time within 5°C of Actual Peak Temperature	30 s
Peak Temperature Range	260°C
Ramp down Rate	6°C/s max
Time 25°C to Peak Temperature	8 minutes max

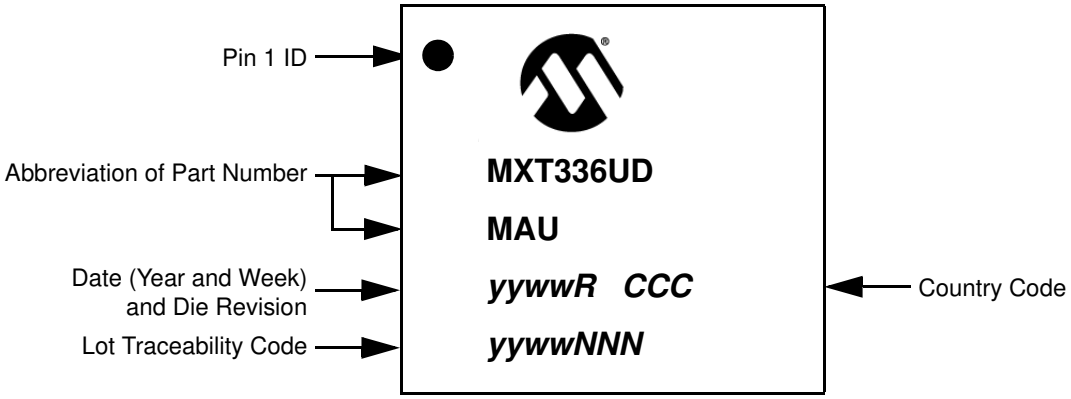
11.13 Moisture Sensitivity Level (MSL)

MSL Rating	Package Type(s)	Peak Body Temperature	Specifications
MSL3	56-pin XQFN	260°C	IPC/JEDEC J-STD-020

12.0 PACKAGING INFORMATION

12.1 Package Marking Information

12.1.1 56-PIN XQFN



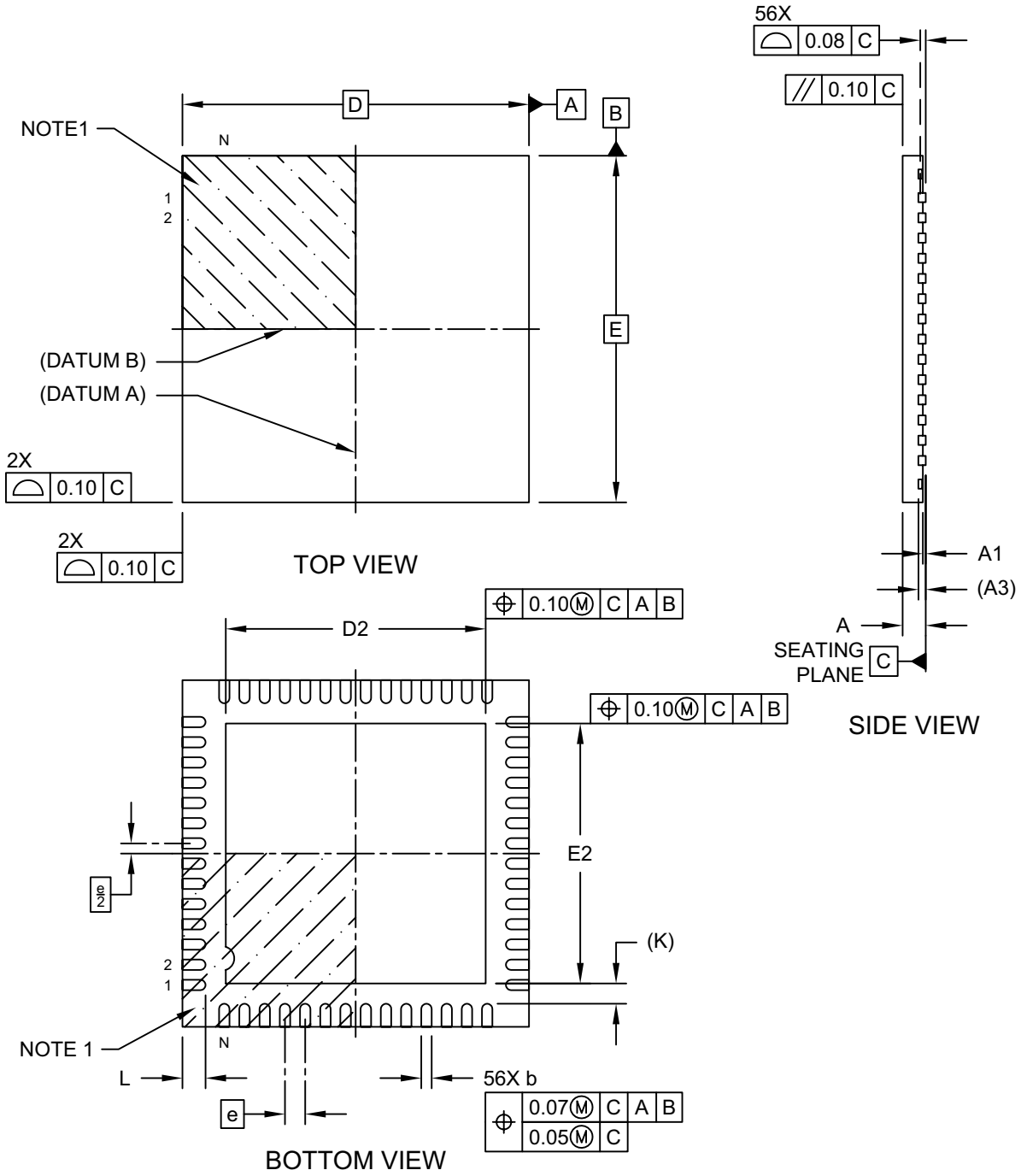
12.1.2 ORDERABLE PART NUMBERS

The product identification system for maXTouch devices is described in “Product Identification System” on page 63. That section also lists example part numbers for the device.

12.2 Package Details

56-Lead Extremely Thin Quad Flatpack No-Lead Package (TWB) - 6x6x0.4 mm Body [XQFN] Wlth 4.5x4.5 mm Exposed Pad; Atmel Legacy Global Package Code ZIX

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-21448 Rev A Sheet 1 of 2

56-Lead Extremely Thin Quad Flatpack No-Lead Package (TWB) - 6x6x0.4 mm Body [XQFN] Wlth 4.5x4.5 mm Exposed Pad; Atmel Legacy Global Package Code ZIX

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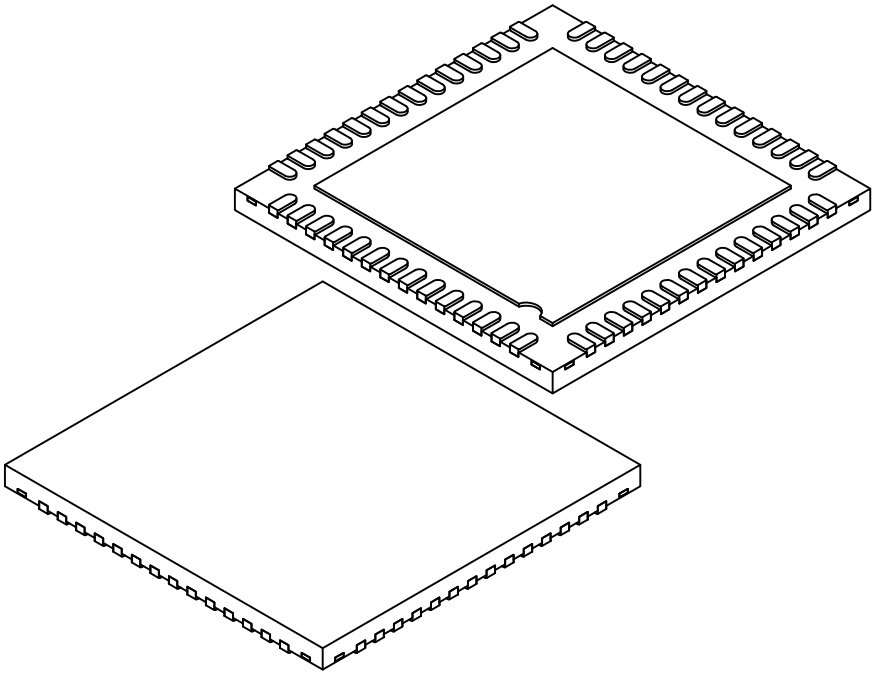


Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N		56	
Pitch	e		0.35 BSC	
Overall Height	A	–	–	0.400
Standoff	A1	0.00	–	0.05
Terminal Thickness	A3		0.127 REF	
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	4.40	4.50	4.60
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	4.40	4.50	4.60
Terminal Width	b	0.13	0.18	0.23
Terminal Length	L	0.35	0.40	0.45
Terminal-to-Exposed-Pad	K		0.35 REF	

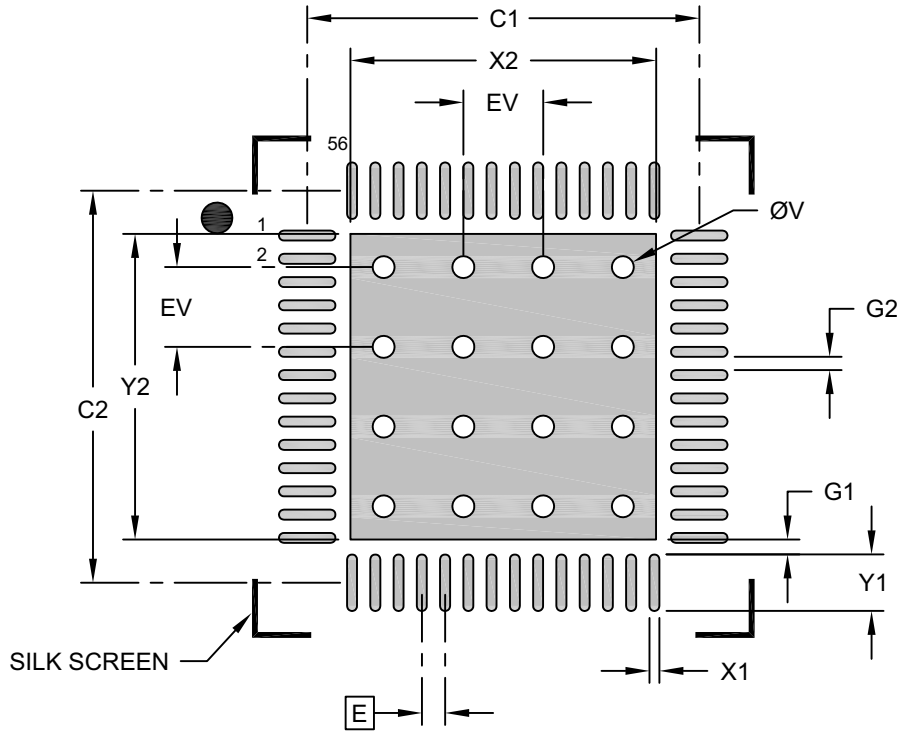
Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-21448 Rev A Sheet 2 of 2

56-Lead Extremely Thin Quad Flatpack No-Lead Package (TWB) - 6x6x0.4 mm Body [XQFN] Wlth 4.5x4.5 mm Exposed Pad; Atmel Legacy Global Package Code ZIX

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.35 BSC	
Optional Center Pad Width	X2			4.60
Optional Center Pad Length	Y2			4.60
Contact Pad Spacing	C1		5.90	
Contact Pad Spacing	C2		5.90	
Contact Pad Width (X56)	X1			0.15
Contact Pad Length (X56)	Y1			0.85
Contact Pad to Center Pad (X56)	G1	0.23		
Contact Pad to Contact Pad (X52)	G2	0.20		
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		1.20	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-23448 Rev A

APPENDIX A: ASSOCIATED DOCUMENTS

Microchip maXTouch Web Site

For general information on the mXT336UD-MAU002, please visit the following:

- https://www.microchip.com/wwwproducts/en/ATMXT336UD

Microchip maXTouch Documents

The following documents are available on the Microchip website.

Touchscreen Design and PCB/FPCB Layout Guidelines

- Application Note: MXTAN0208 – *Design Guide for PCB Layouts for maXTouch Touch Controllers*
- Application Note: QTAN0080 – *Touchscreens Sensor Design Guide*
- Application Note: AN2683 – *Edge Wiring for Self Capacitance maXTouch Touchscreens*

Configuring and Tuning the Device

- Application Note: MXTAN0213 – *Interfacing with maXTouch Touchscreen Controllers*

Tools

- *maXTouch Studio User Guide* (accessible as on-line help from within maXTouch Studio)

External Documents

The following documents are not supplied by Microchip. To obtain any of the following documents, please contact the relevant organization.

Communication Interface

- UM10204, *I^2C bus specification and user manual*, Rev. 6 — 4 April 2014
  Available from NXP

APPENDIX B: REVISION HISTORY

Revision A (March 2022)

Initial edition for firmware revision 2.0.AA – Release

INDEX

PRODUCT IDENTIFICATION SYSTEM

The table below gives details on the product identification system for maXTouch devices. See "Orderable Part Numbers" below for example part numbers for the mXT336UD-MAU002.

To order or obtain information, for example on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	–XXX	[X]	[X]	[XXX]
Device	Package	Temperature Range	Tape and Reel Option	Pattern

Device:	Base device name		
Package:	CC	=	UFBGA (Ultra Thin Fine-pitch Ball Grid Array)
	C2	=	UFBGA (Ultra Thin Fine-pitch Ball Grid Array)
	NH	=	UFBGA (Ultra Thin Fine-pitch Ball Grid Array)
	C4	=	X1FBGA (Extra Thin Fine-pitch Ball Grid Array)
	MA	=	XQFN (Super Thin Quad Flat No Lead Sawn)
	MA5	=	XQFN (Super Thin Quad Flat No Lead Sawn)
Temperature Range:	U	=	–40°C to +85°C (Grade 3)
	T	=	–40°C to +85°C (Grade 3)
	B	=	–40°C to +105°C (Grade 2)
Tape and Reel Option:	*Blank*	=	Standard Packaging (Tube or Tray)
	R	=	Tape and Reel (1)
Pattern:	Extension, QTP, SQTP, Code or Special Requirements (Blank Otherwise)		

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. See "Orderable Part Numbers" below or check with your Microchip Sales Office for package availability with the Tape and Reel option.

Orderable Part Numbers

Orderable Part Number	Firmware Revision	Description
ATMXT336UD-MAU002 (Supplied in trays)	2.0.AA	56-pin XQFN 6 × 6 × 0.4 mm, RoHS compliant Industrial grade; not suitable for automotive characterization
ATMXT336UD-MAUR002 (Supplied in tape and reel)		

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- **Product Support** – Datasheets and errata, application notes and sample programs, design resources, user's guides and hardware support documents, latest software releases and archived software
- **General Technical Support** – Frequently Asked Questions (FAQ), technical support requests, online discussion groups, Microchip consultant program member listing
- **Business of Microchip** – Product selector and ordering guides, latest Microchip press releases, listing of seminars and events, listings of Microchip sales offices, distributors and factory representatives

THE MAXTOUCH WEB SITE

Information on Microchip's maXTouch product line can be accessed via the microchip web site at www.microchip.com, This information is also available for direct access via a short-cut at www.maxtouch.com. The maXTouch web pages contain the following information:

- **Product Information** – Product specifications, brochures, datasheets, protocol guides
- **Tools and Software** – Evaluation kits, maXTouch Studio, software libraries for individual maXTouch touch controllers
- **Training and Support** – Generic application notes and training material for the maXTouch product range

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